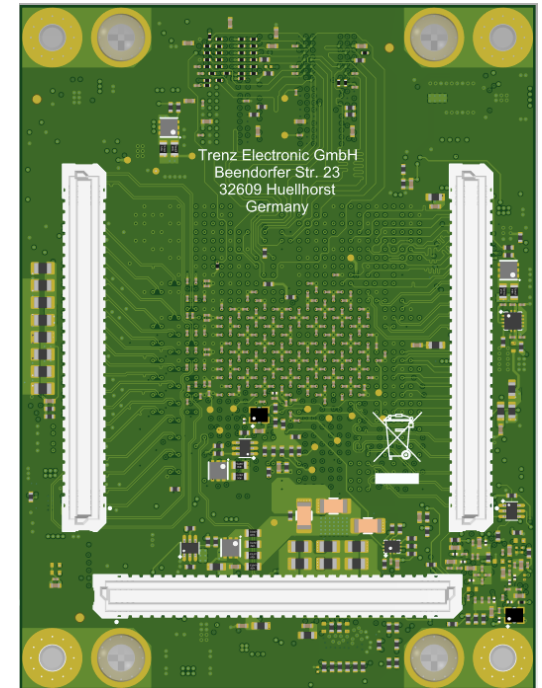
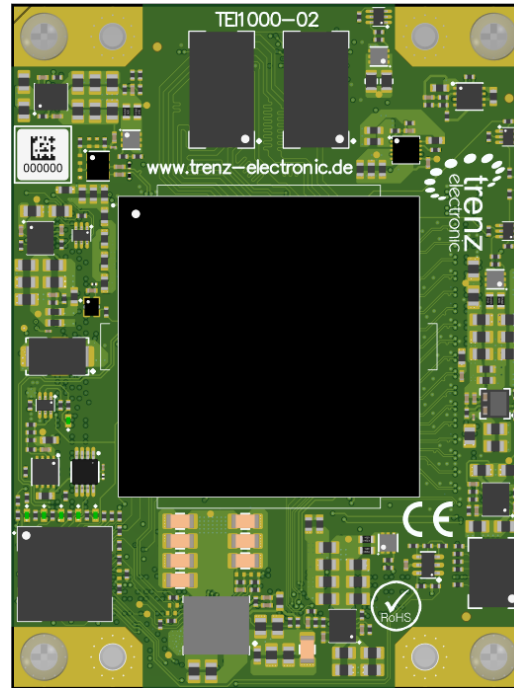
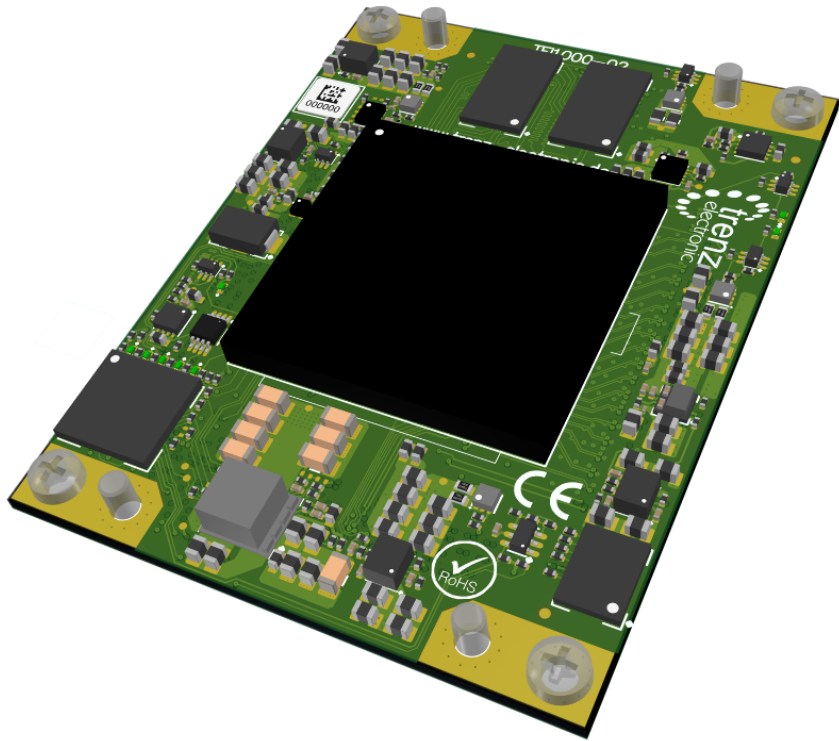


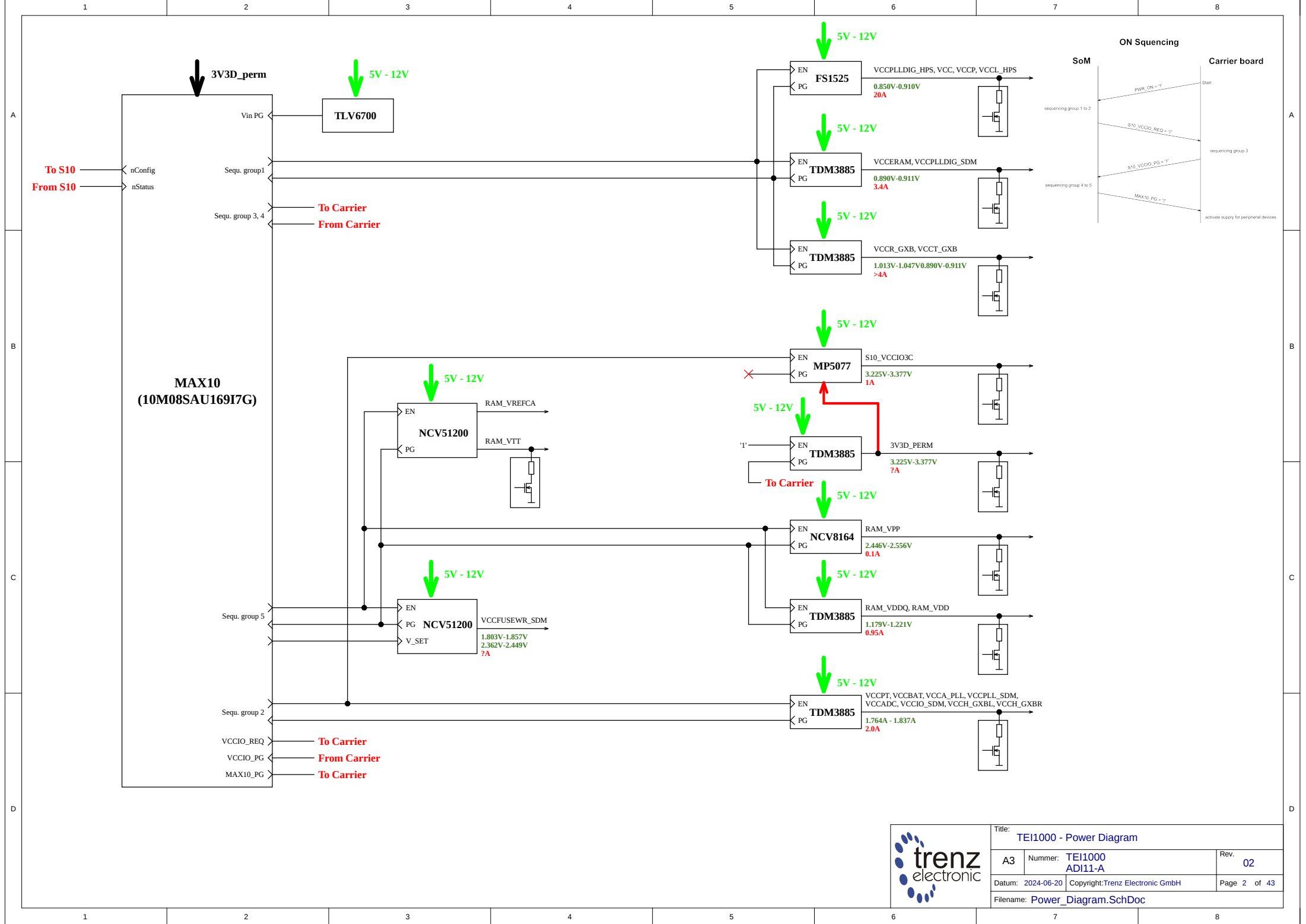


Regarding the usage of our schematics and alike documentation for Trenz module TEI1000.

Project is protected under copyright and we strongly and strictly prohibit the reverse engineering or recreation, even if the design is just adapted or modified. TEI1000 is protected under such right and in case of plagiarism we will have to do anything necessary in order to protect our assets.

Schematics and other handouts serve for informational purposes only!

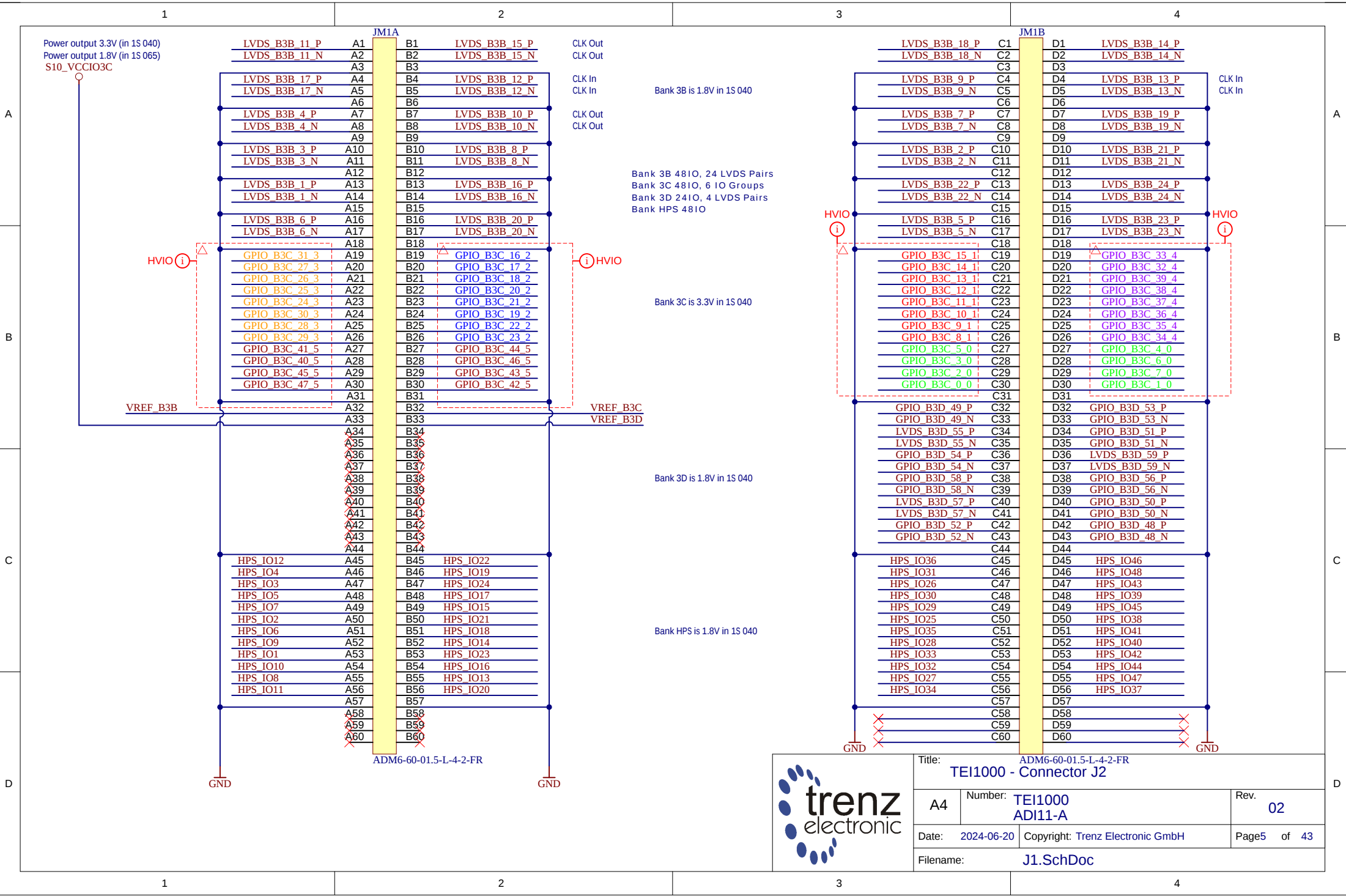
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	A4	Number: TEI1000 ADI11-A	Rev. 02
	Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Page 1 of 43
	Filename: Legal Notices Modules.SchDoc		

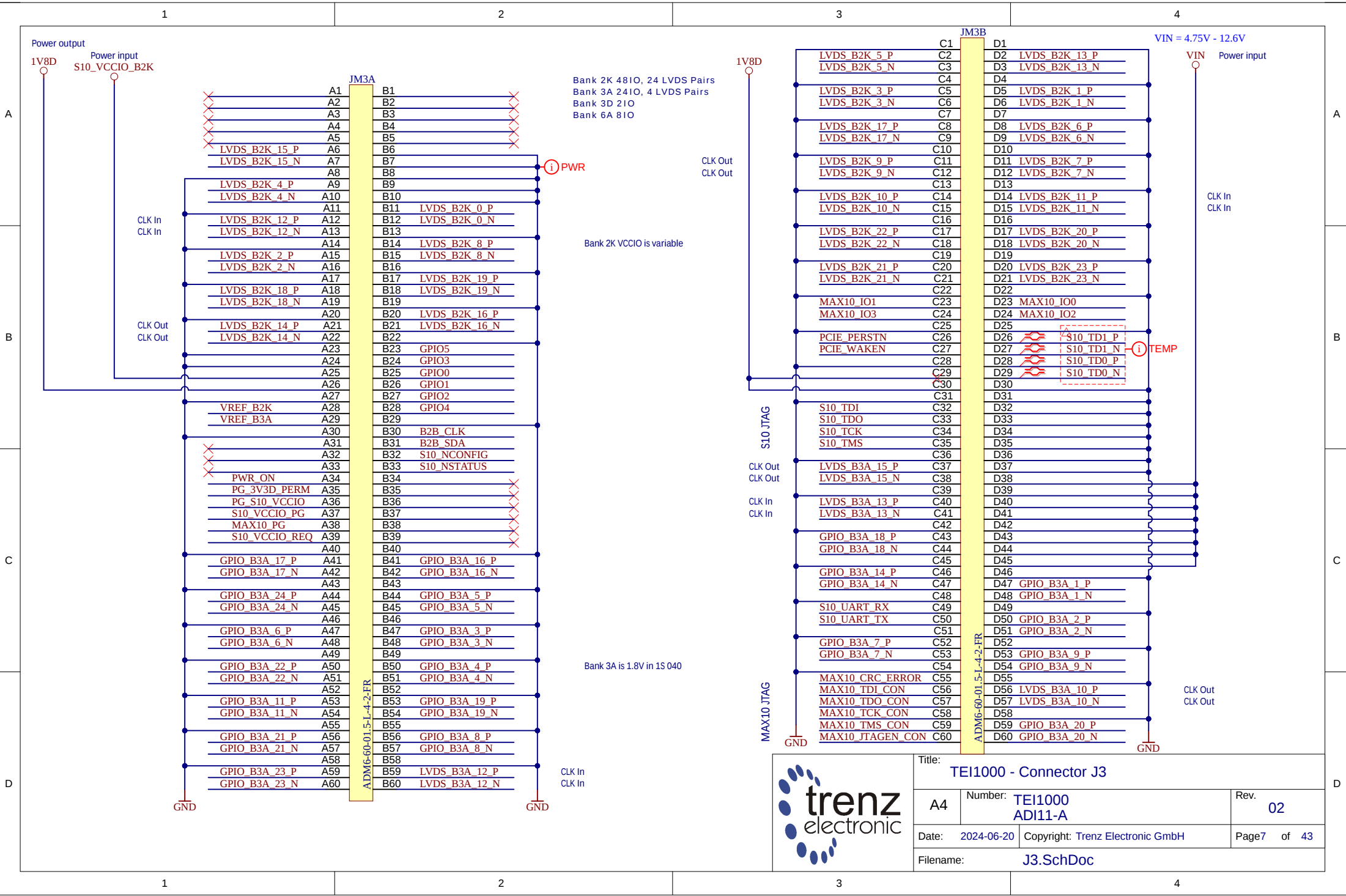


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A3	Number: TEI1000 ADI11-A	Rev. 02
Datum: 2024-06-20	Copyright: Trenz Electronic GmbH	Page 2 of 43
Filename: Power_Diagram.SchDoc		

1		2		3		4	
A	REV		Description				
B	02	- Changed pulldowns to 1K for all power sequencing groups. Corrected notes about enable thresholds of voltage regulators and load switches. - Changed value for R191-195 to 0R - Added 100pF MAX10 JTAG TCK to GND. Comp. C88 - Removed T6A from Net MAX10_nCONFIG. - Swapped R184 with R186. Upper side 150R, lower side 100R for voltage divider. - Added filtered monitoring of 1.03V power rail by MAX10. - Changed LED D1 to color green. Same like other LEDs. - Fixed group length matching issue of ADD/CMD signals between S10 and first DRAM-Chip. - Replaced RAM-RefClock oscillator (Y1) by 125MHz LVDS oscillator for SX variant and 100MHz LVDS GX variant - Replaced TDM3883 GXB regulator with TDM3885 type - Replaced VCC_CORE voltage regulator by FS1525. Used schematic from TDK User Guide as reference - Moved R180 out of connector J3 - Drew overview diagram in Altium instead of adding SVG-Image at overview sheet. - Updated overview sheet - Added 100R bleeding resistor R228 (AN 22507) from VCC_CORE rail to GND - Connected R175.2 to U20.6/U20.11 instead of net "S10_VCCIO3C". Added 0R jumper R234 (AN 22738) between "3V3D_PERM" and U20.6/U20.11. Set R175 to DNP. Set R234 to populated. - Added 0402 499R (AN 27123) pull-down resistors to TEN pins (U1A.TEN, U2A.TEN) (R229, 230). - Pin U4A.D2 (ANAIN1), U4.H4 (CLK1P), U4.H5 (CLK1N), U4.N2 (DPCLK0) and U4.L3 (CLKOUTP) connected to GND. - Replaced R227 and R224 by 4k99 (AN 22754). - Separated AGND and PGND of U12: U12.(64-69) -> AGND, U12.(31,32,33,34,35,36,37,58,59,60,61,62,36) -> GND. Connected AGND to GND by net-tie V12 (AN 30278) under U12 in layout. Connected to AGND: R226.2 (PS-resistor), R225.2 (ADDR-resistor), R222.2 (FB-LS-resistor). - Added 4k99 pull-up (AN 22754) from VCC to ALERT-pin of FS15625 (U12.28) - Added test points to CLKOUT- and ISHRE-pin of FS1525 (U12.29, U12.20) (TP7, TP9) - Replaced R72 by 1k resistor (AN 22752). - Added note about power consumption of 3V3D_PERM-rail. - Added note about purpose of R175. - Added note about slave address and Fsw of FS1525. - Connected unused GXB receiver pins to GND. (U14.(N32, N31, M30, M29, H30, H29, F30, F29, D30, D29, B30, B29)) - Added note about supply voltage range of bank 2K. - Added 0R jumper R235 (AN 22738) between VTT and VREFB2MN0. Added 0R jumper R236 (AN 22738) between VTT and VREFB2NN0. - Added note about logic levels of PCIE_PERSTN and PCIE_WAKEN, as well as necessarily of level shifters on carrier board for these signals. - Added DNP 10k PUs (R232, R233) (AN 22750) to QSPI_R_IO3 and QSPI_R_IO2. - Added test point to voltage rails: VCC_CORE (TP18), 1V8_FLT1 (TP19), 1V8_FLT2 (TP20), VCCPLLDIG_SDM (TP21). - Added return path vias next to layer jump of diff pair DDR4-IP_CLK - Improved entries to pads of U11. - Fixed courtyard intersections where possible. - Merged GND polygons near U10. - Added additional return path vias next to layer jumps of GXB-pairs, where possible. - Added anti-pad keptouts to GXB-related diff-pair layer jump vias. - Removed splits in reference planes for impedance controlled signals where possible.				MSt	
		- Added test points to the voltage rails on the TOP side - Changed DCDC (U6) TDM3885XUMA1 (Ioutmax=4A)-> FS1606-0600-AL (Ioutmax=6A). - Added I2C connection (signals B2B_CLK & B2B_SDA) DCDC U6 to MAX10 (U4.M10 & U4.N12) , B2B connector (J3.B30 & J3.B31) - Moved Net-Tie V11(signal "EN_S10_VCCFUSEWR_SDM") from "EN5" to "EN3" - Full update Library				VT	
C							
D			Title: TEI1000 – Revision_Changes			D	
			A4	Number: TEI1000 ADI11-A	Rev. 02		
			Date: 09.07.2024	Copyright: Trenz Electronic GmbH	Page 3 of 43		
			Filename: Revision_Changes.SchDoc				
1		2		3		4	

1	2	3	4
U_J1 J1.SchDoc U_J2 J2.SchDoc U_J3 J3.SchDoc U_DDR4-TERM DDR4-TERM.SchDoc U_Bank_1C Bank_1C.SchDoc U_Bank_1D Bank_1D.SchDoc U_Bank_1E Bank_1E.SchDoc U_Bank_1F Bank_1F.SchDoc U_Bank_2K Bank_2K.SchDoc U_Bank_2L Bank_2L.SchDoc U_Bank_2M Bank_2M.SchDoc RAM / RAM-CLK U_Bank_2N Bank_2N.SchDoc RAM U_Bank_3A Bank_3A.SchDoc PM1 PM2 FIDU-DOT - mini PM3 FIDU-DOT - mini PM4 FIDU-DOT - mini PM5 FIDU-DOT - mini PM6 FIDU-DOT - mini FIDU-DOT - mini	U_POWER_Discharging_3 POWER_Discharging_3.SchDoc U_POWER_Discharging_2 POWER_Discharging_2.SchDoc U_POWER_Discharging_1 POWER_Discharging_1.SchDoc U_POWER_Decoupling_1 POWER_Decoupling_1.SchDoc U_POWER_Decoupling_2 POWER_Decoupling_2.SchDoc U_POWER_Decoupling_3 POWER_Decoupling_3.SchDoc U_POWER_Decoupling_4 POWER_Decoupling_4.SchDoc U_DDR4-RAM DDR4-RAM.SchDoc U_DDR4-RAM_2 DDR4-RAM_2.SchDoc U_PD Power_Diagram.SchDoc U_Bank_3B Bank_3B.SchDoc U_Bank_6A Bank_6A.SchDoc U_Bank_3D Bank_3D.SchDoc U_Bank_SDM Bank_SDM.SchDoc U_REV_CH Revision_Changes.SchDoc MECH1 TE Address Overlay LOGO ADDRESS LOGO1 TE Logo PRINT Layer LOGO PRINT Serial1 Serial Serialnumber 6,3 x 6.3mm UKCA UKCA Logo on Top Overlay UKCA-TOPOVERLAY	U_LN Legal Notices Modules.SchDoc U_POWER_Sequencing_3 POWER_Sequencing_3.SchDoc U_POWER_Sequencing_1 POWER_Sequencing_1.SchDoc U_POWER_Sequencing_2 POWER_Sequencing_2 U_POWER_1 POWER_1.SchDoc U_POWER_Decoupling_4 Power_Sequencing_filtering.SchDoc U_POWER_2 POWER_2.SchDoc U_POWER_3 POWER_3.SchDoc U_POWER_4 POWER_4.SchDoc U_Misc Misc.SchDoc U_Bank_3C Bank_3C.SchDoc U_Bank_HPS Bank_HPS.SchDoc U_FPGA_POWER_1 FPGA_POWER_1.SchDoc U_FPGA_POWER_2 FPGA_POWER_2.SchDoc Special notes:	H1 Mount.Hole 3.2mm für Unterlegscheibe H2 Mount.Hole 3.2mm für Unterlegscheibe H3 Mount.Hole 3.2mm für Unterlegscheibe H4 Mount.Hole 3.2mm für Unterlegscheibe H5 Mount.Hole 3.2mm für Unterlegscheibe H6 Mount.Hole 3.2mm für Unterlegscheibe H7 Mount.Hole 3.2mm für Unterlegscheibe H8 Mount.Hole 3.2mm für Unterlegscheibe Assembly variant ADI11-A Created by VT Modified by VT Modified at 2024-05-08 SVN Revision 19891 Title: TEI1000 A4 Number: TEI1000 ADI11-A Rev. 02 Date: 2024-06-20 Copyright: Trenz Electronic GmbH Page4 of 43 Filename: TEI1000.SchDoc
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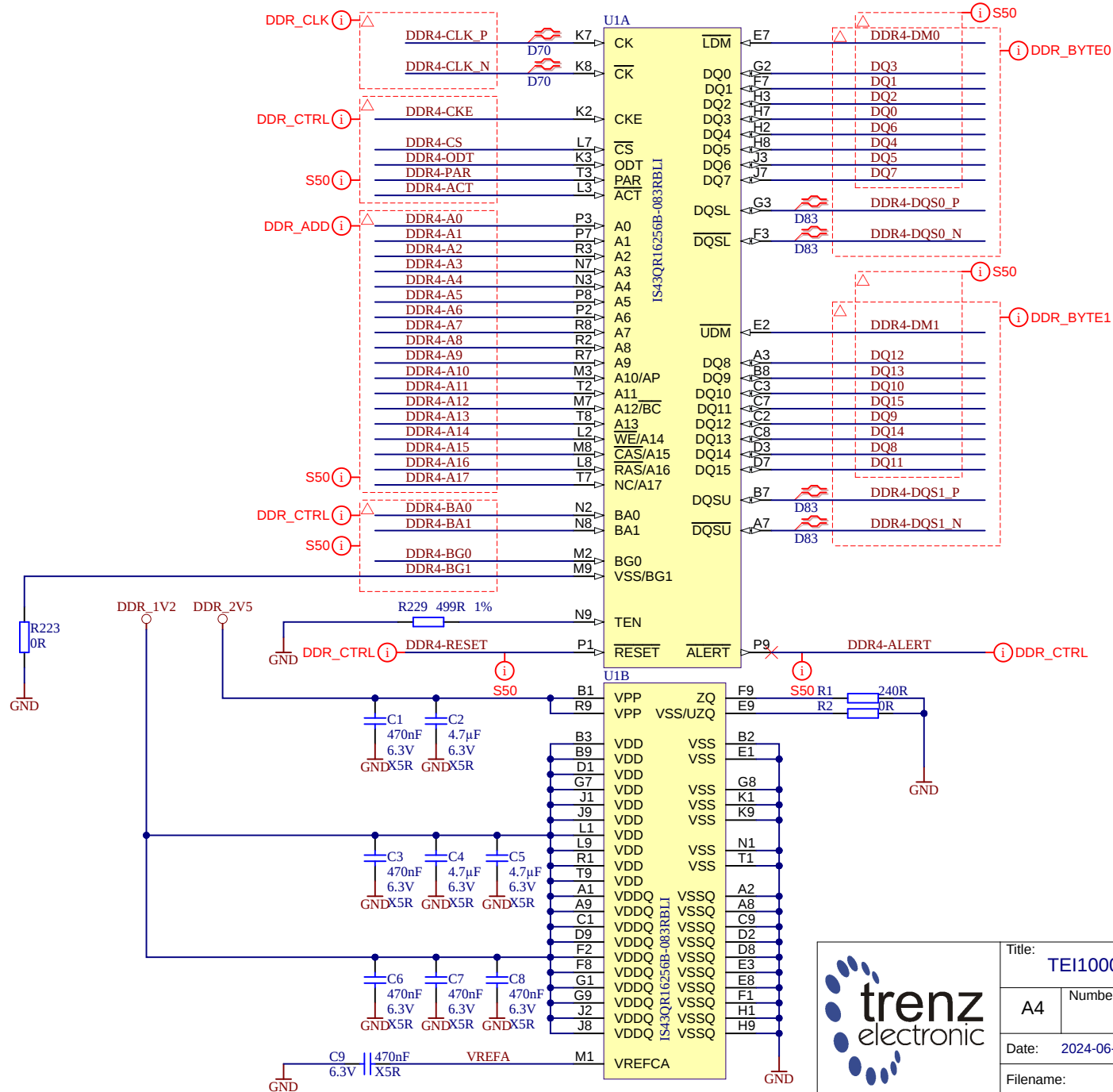
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Date: 2024-06-20	Copyright: Trenz Electronic GmbH		Page7 of 43
Filename: J3.SchDoc			

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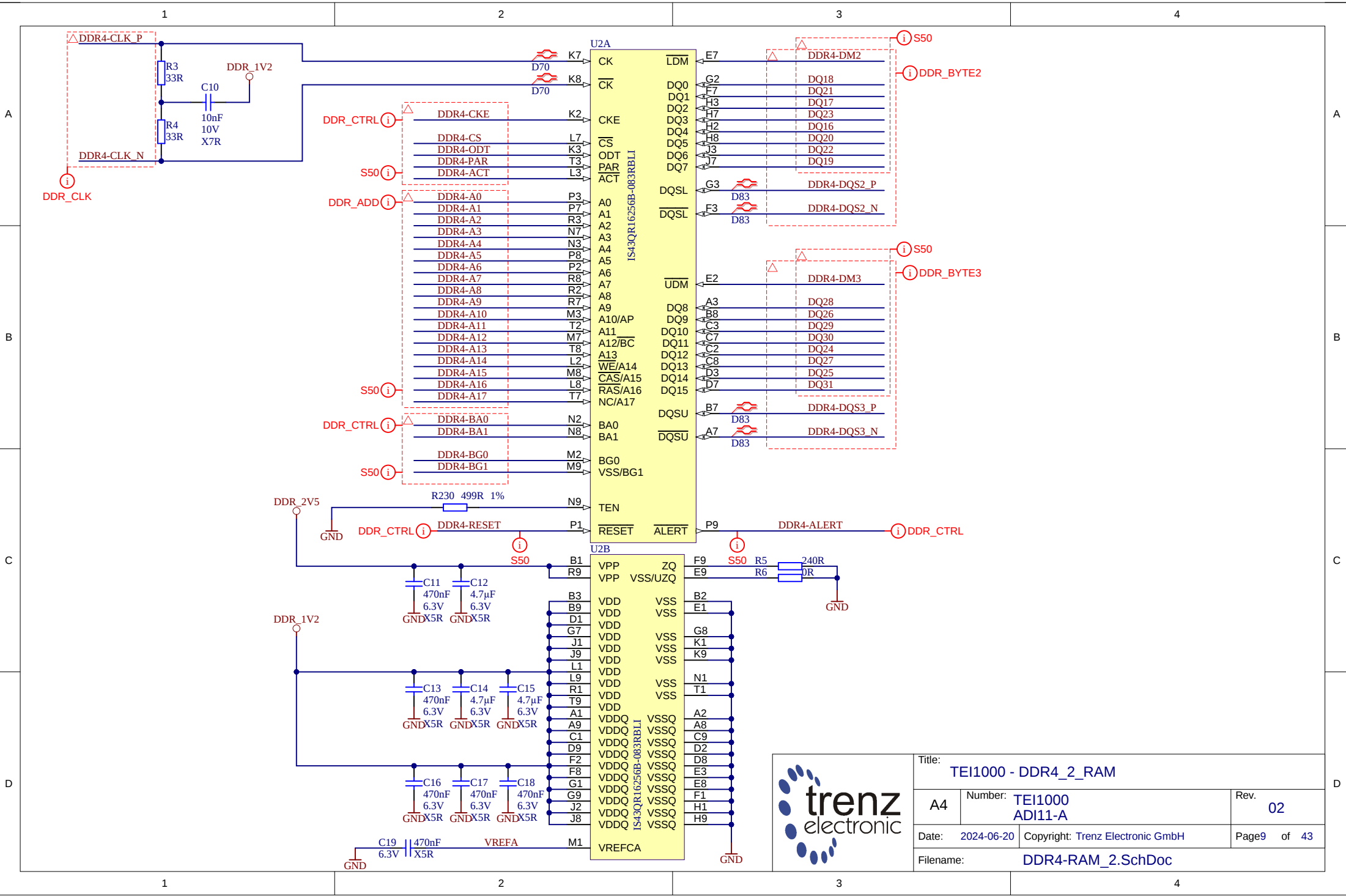
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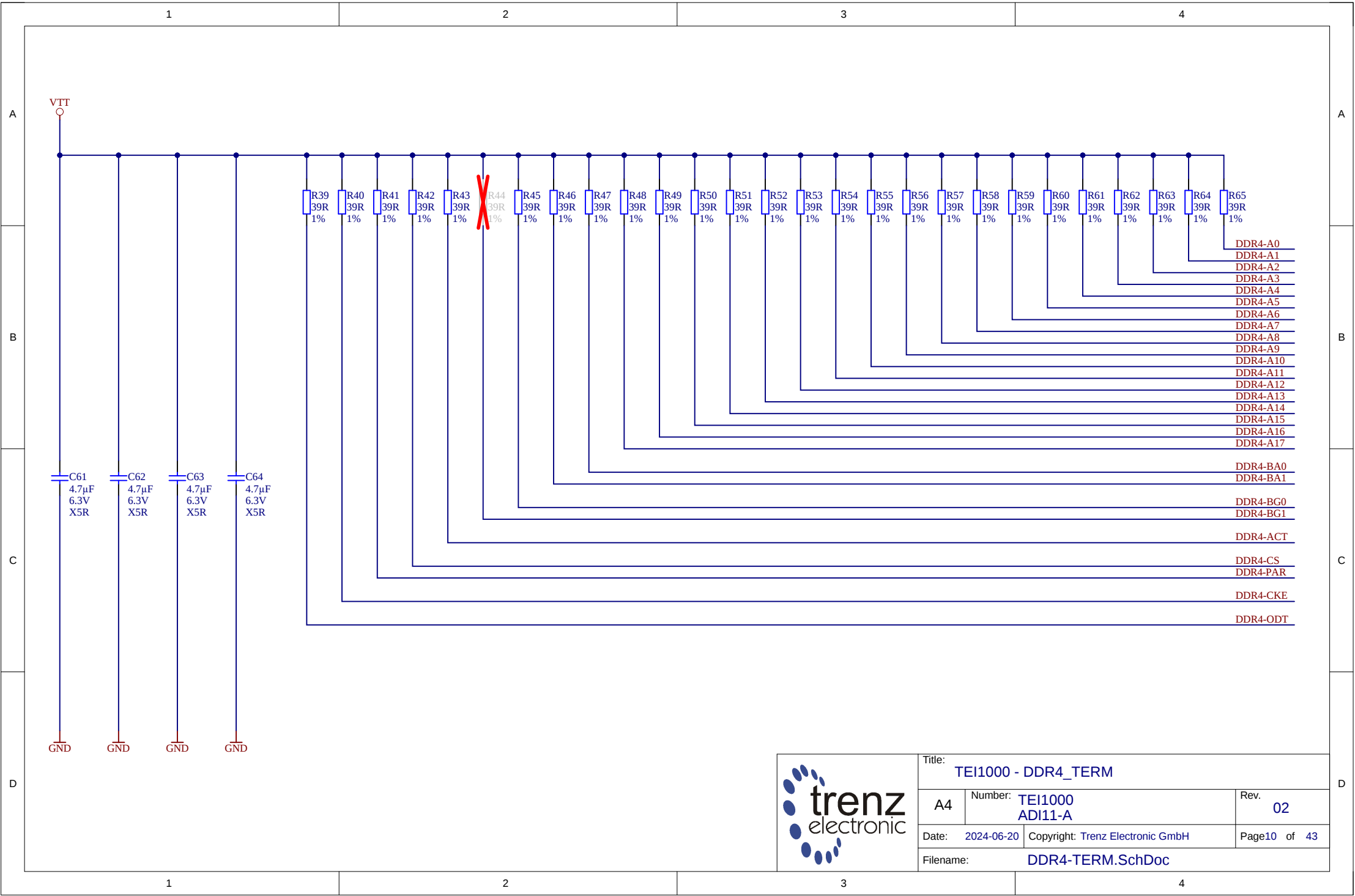
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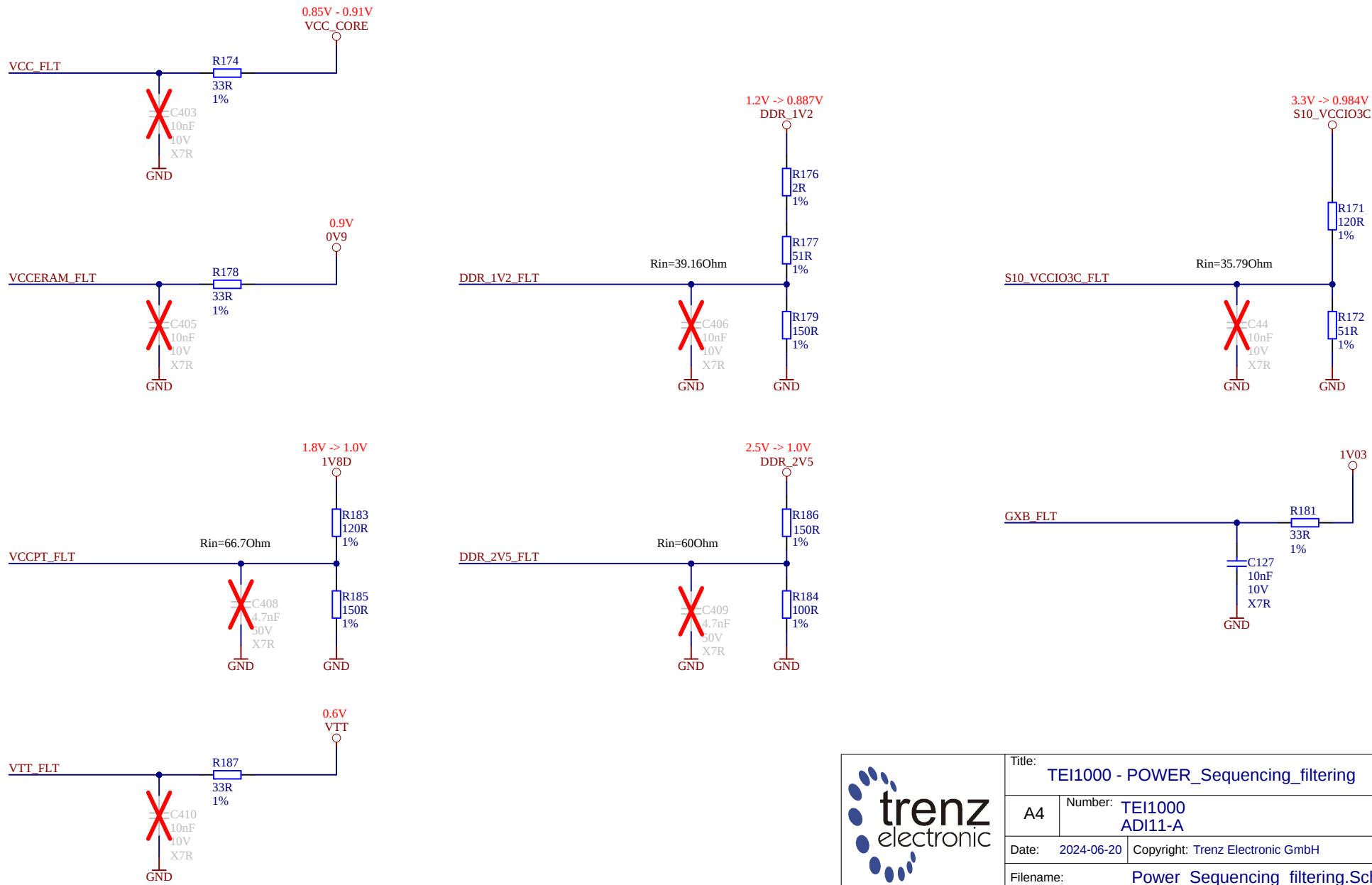
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Date: 2024-06-20	Copyright: Trenz Electronic GmbH		Page 8 of 43
Filename: DDR4-RAM.SchDoc			



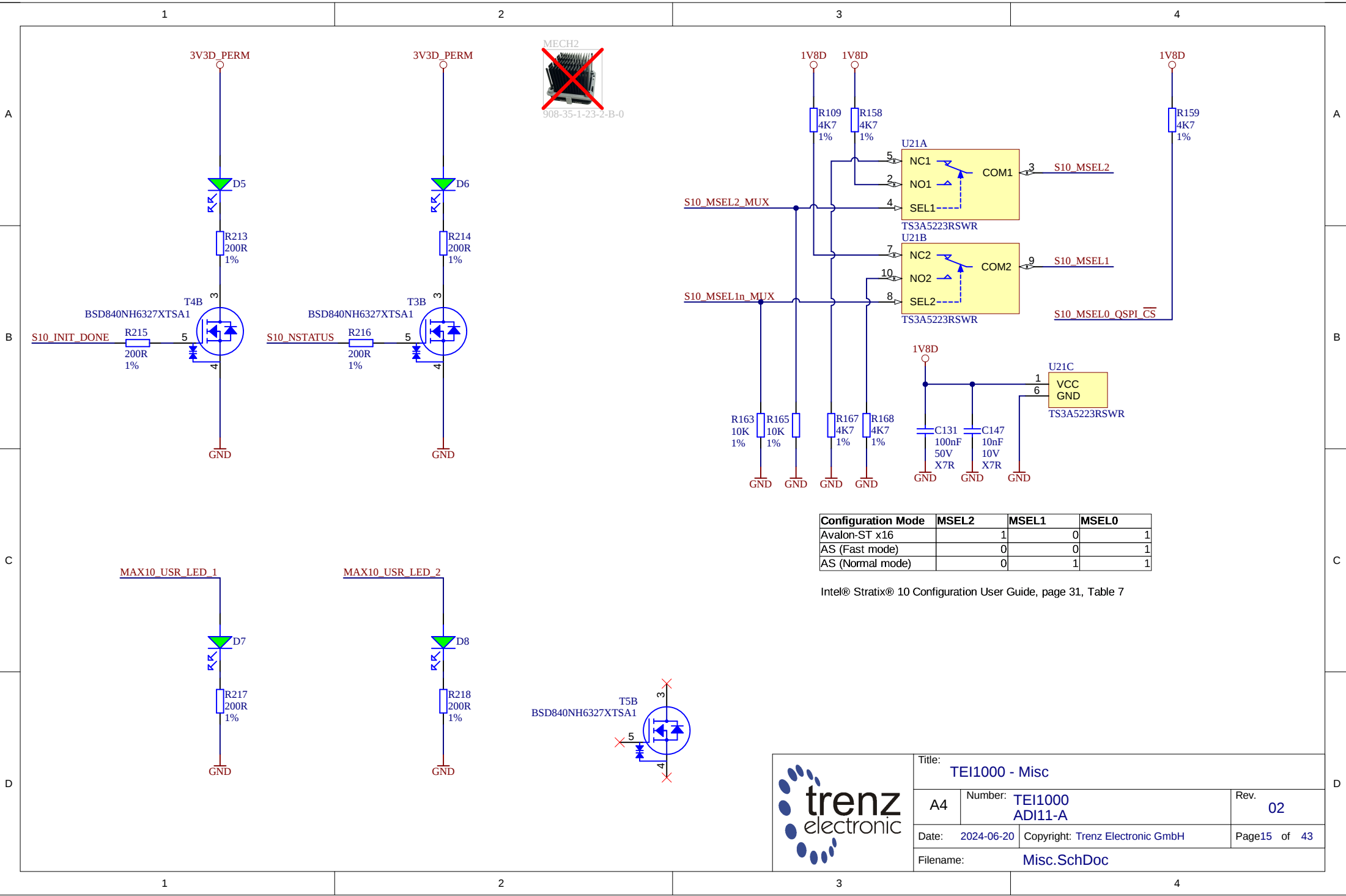
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Date: 2024-06-20	Copyright: Trenz Electronic GmbH		Page 9 of 43
Filename: DDR4-RAM_2.SchDoc			







				Title: TEI1000 - POWER Sequencing_filtering	
A4	Number: TEI1000 ADI11-A			Rev. 02	
Date:	2024-06-20	Copyright: Trenz Electronic GmbH			Page14 of 43
Filename:		Power Sequencing_filtering.SchDoc			



Configuration Mode	MSEL2	MSEL1	MSEL0
Avalon-ST x16	1	0	1
AS (Fast mode)	0	0	1
AS (Normal mode)	0	1	1

Intel® Stratix® 10 Configuration User Guide, page 31, Table 7



Title:
TEI1000 - Misc

A4

Number:
TEI1000
ADI11-A

Rev.
02

Date:
2024-06-20

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Filename:

Misc.SchDoc

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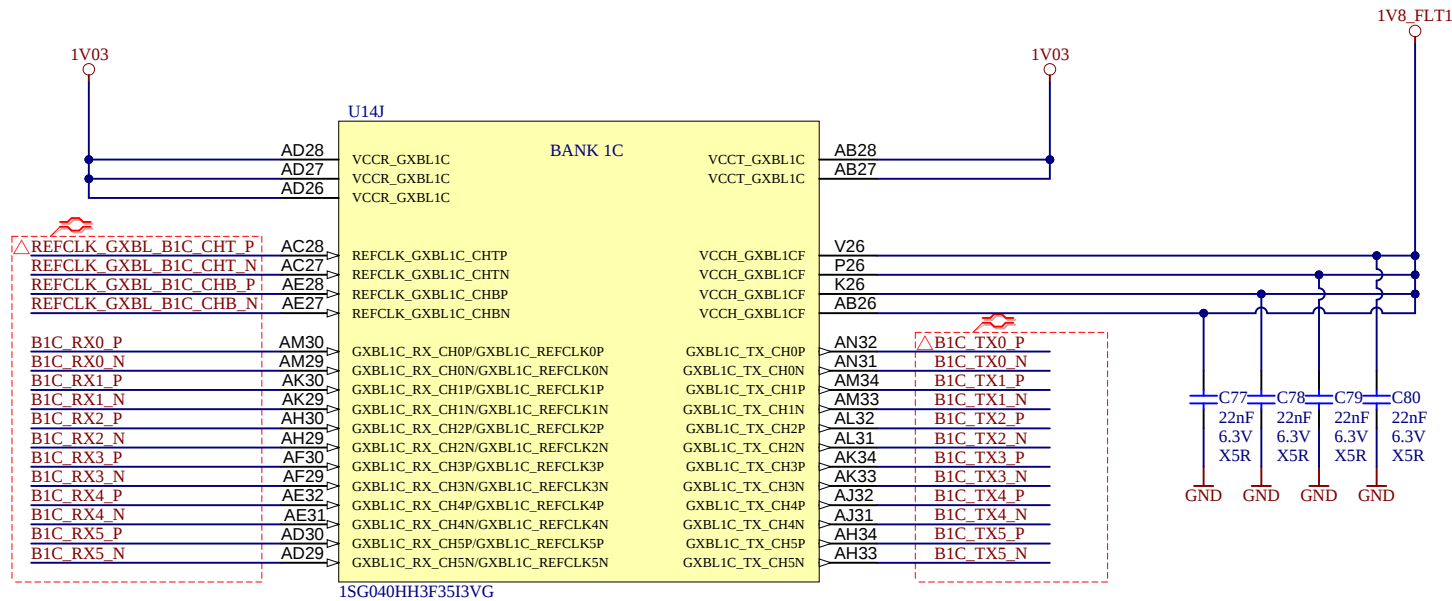
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		A4	Number: TEI1000 ADI11-A
Date: 2024-06-20		Copyright: Trenz Electronic GmbH	
Filename: Bank_1C.SchDoc		Page16 of 43	
		Rev. 02	

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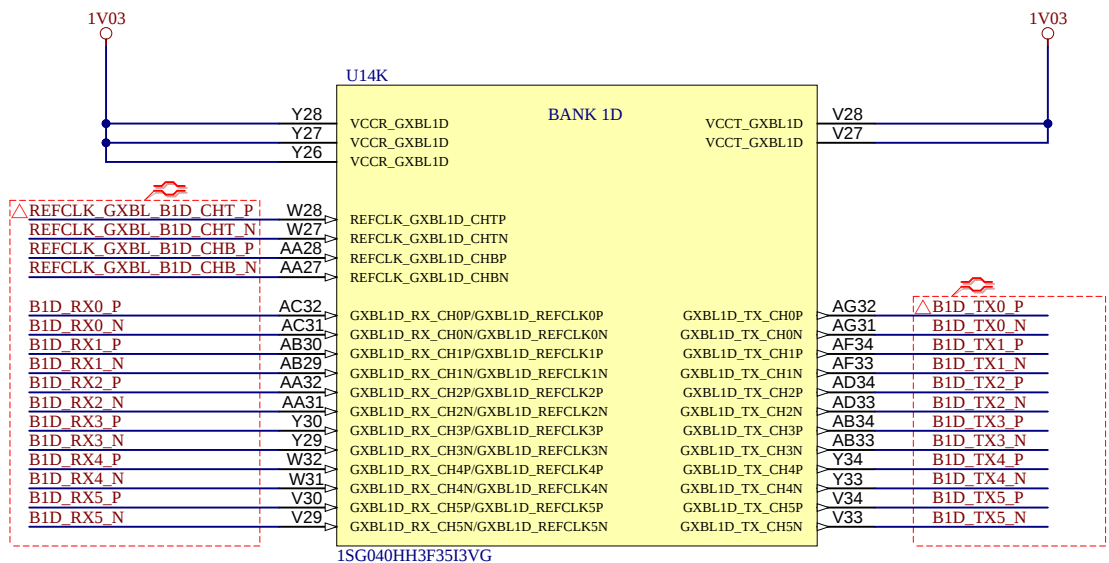
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		A4	Number: TEI1000 ADI11-A
Date: 2024-06-20		Copyright: Trenz Electronic GmbH	
Filename: Bank_1D.SchDoc		Page17 of 43	
		Rev. 02	

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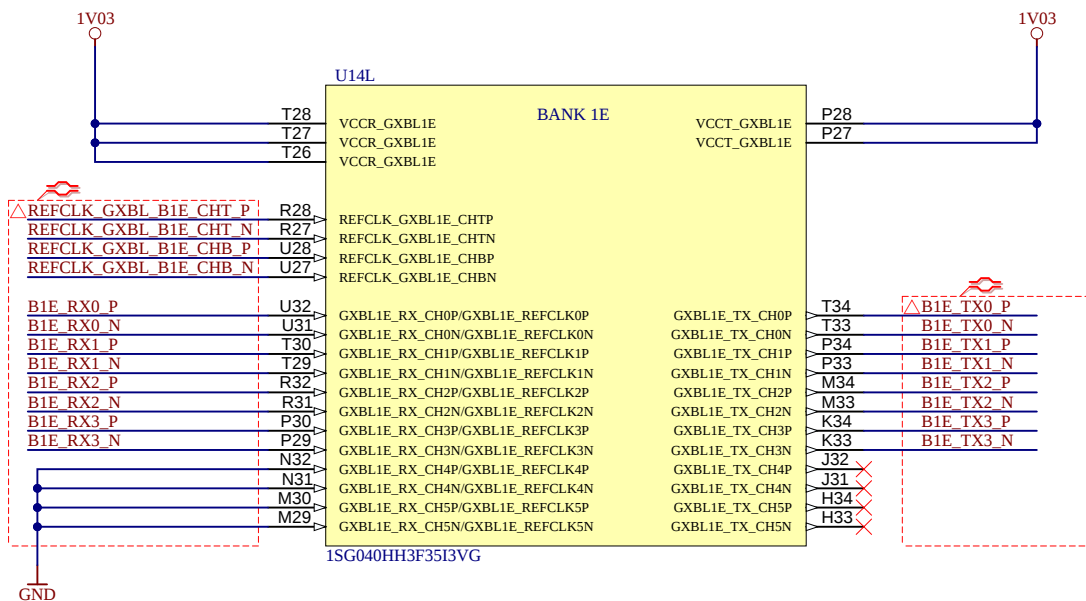
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	A4	Number: TEI1000 ADI11-A
Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Rev. 02
Filename: Bank_1E.SchDoc		Page18 of 43

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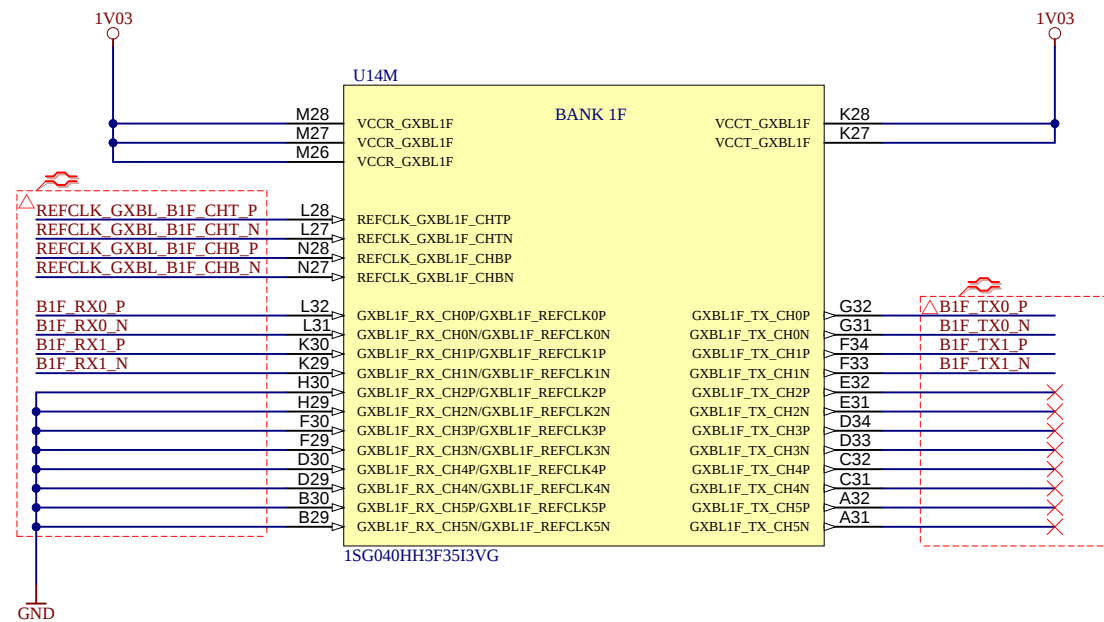
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Date: 2024-06-20	Copyright: Trenz Electronic GmbH	
Filename: Bank_1F.SchDoc		Page19 of 43

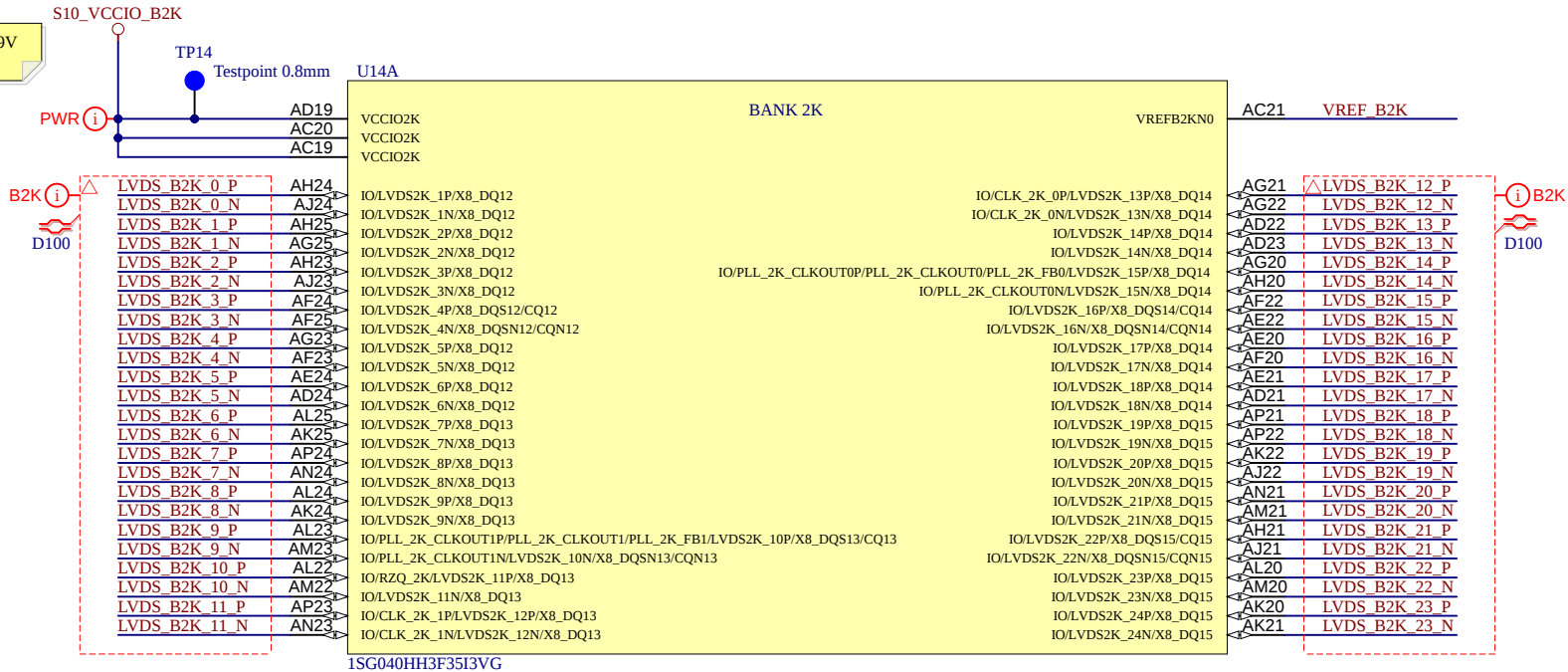
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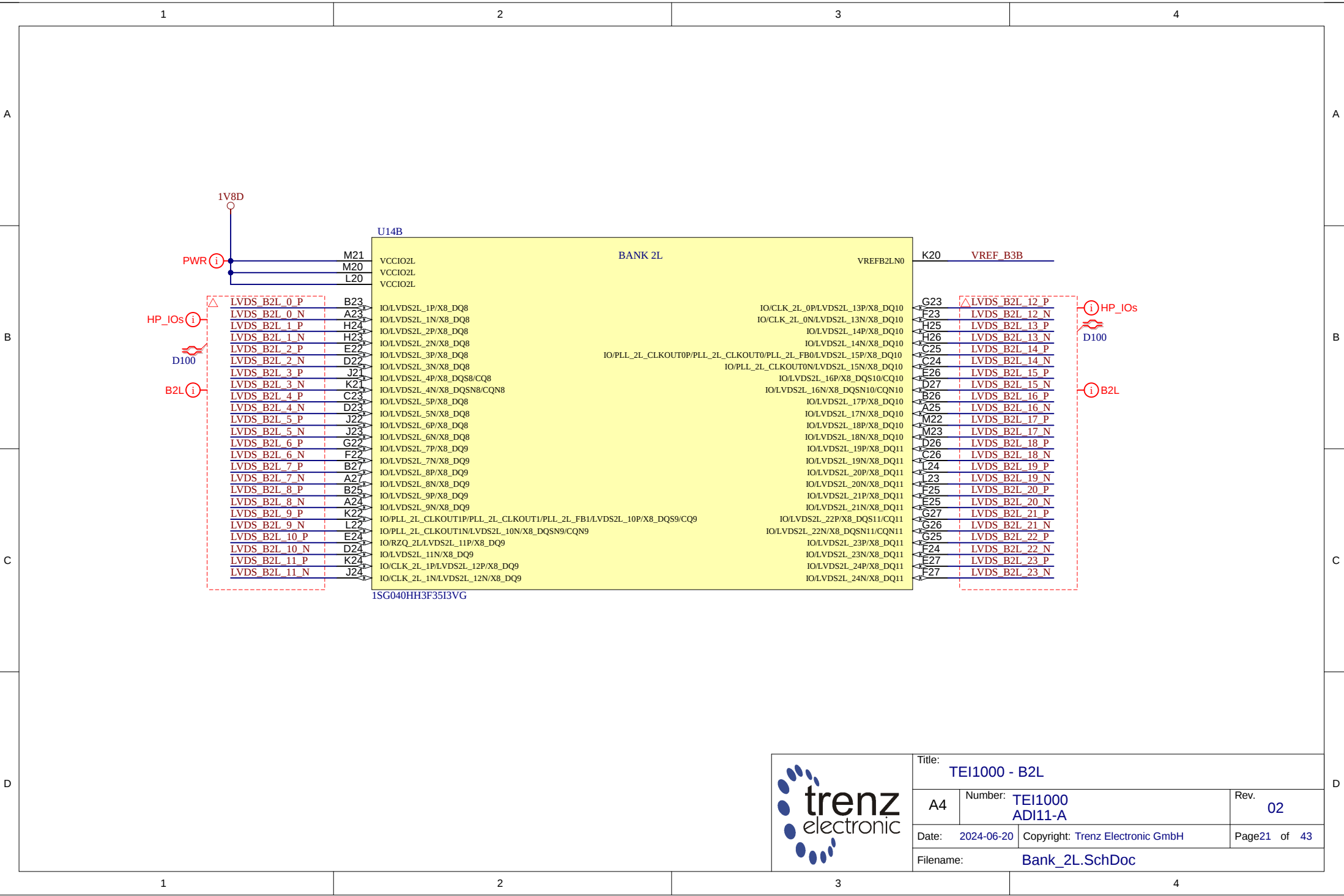
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S10_VCCIO_B2K: 1.14 to 1.89V
(S10 datasheet, page 11)



Title: TEI1000 - B2K			
A4	Number: TEI1000 ADI11-A	Rev. 02	
Date: 2024-06-20	Copyright: Trenz Electronic GmbH		Page20 of 43
Filename: Bank_2K.SchDoc			



Title: TEI1000 - B2L		
A4	Number: TEI1000 ADI11-A	Rev. 02
Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Page21 of 43
Filename: Bank_2L.SchDoc		

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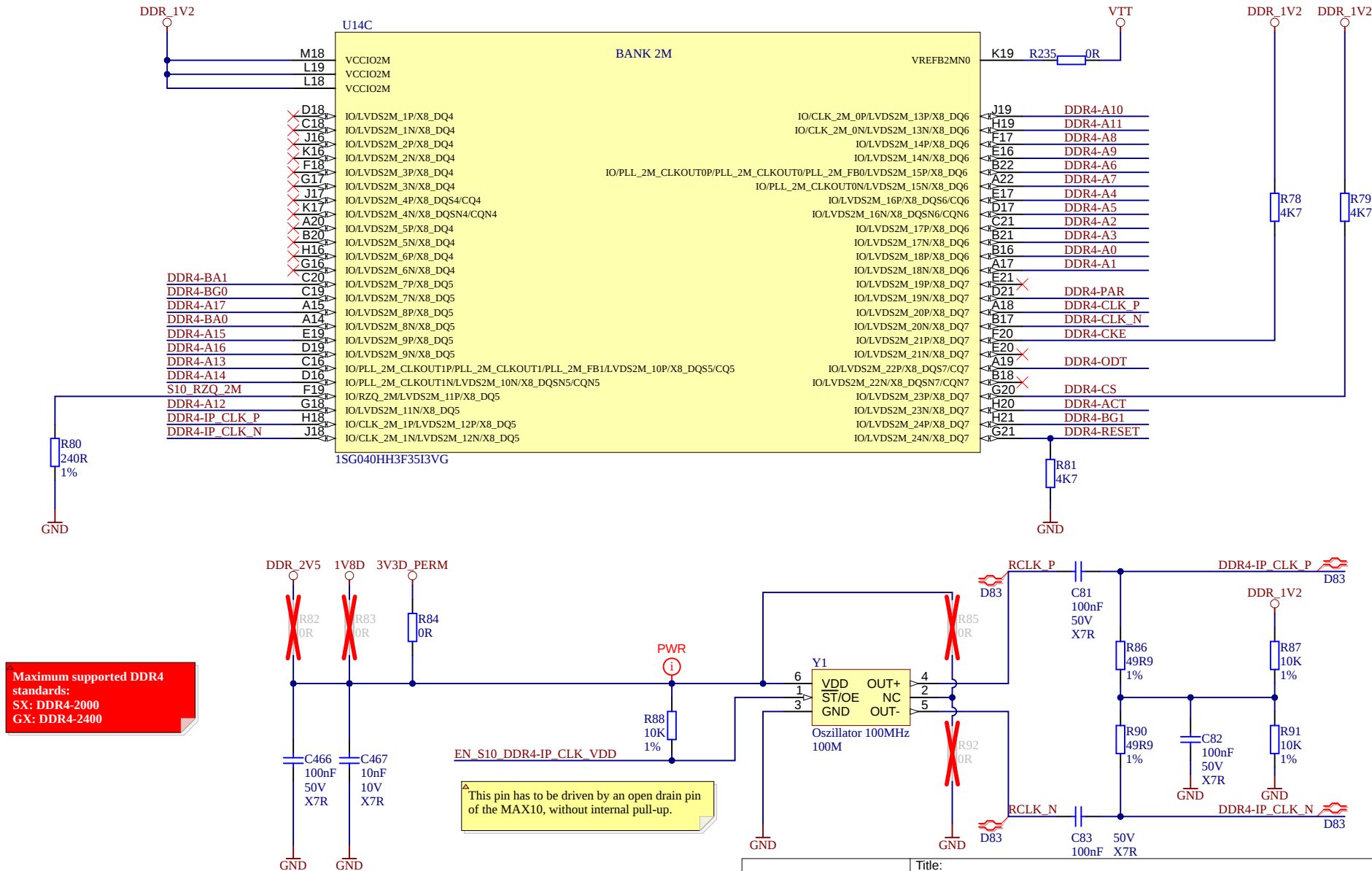
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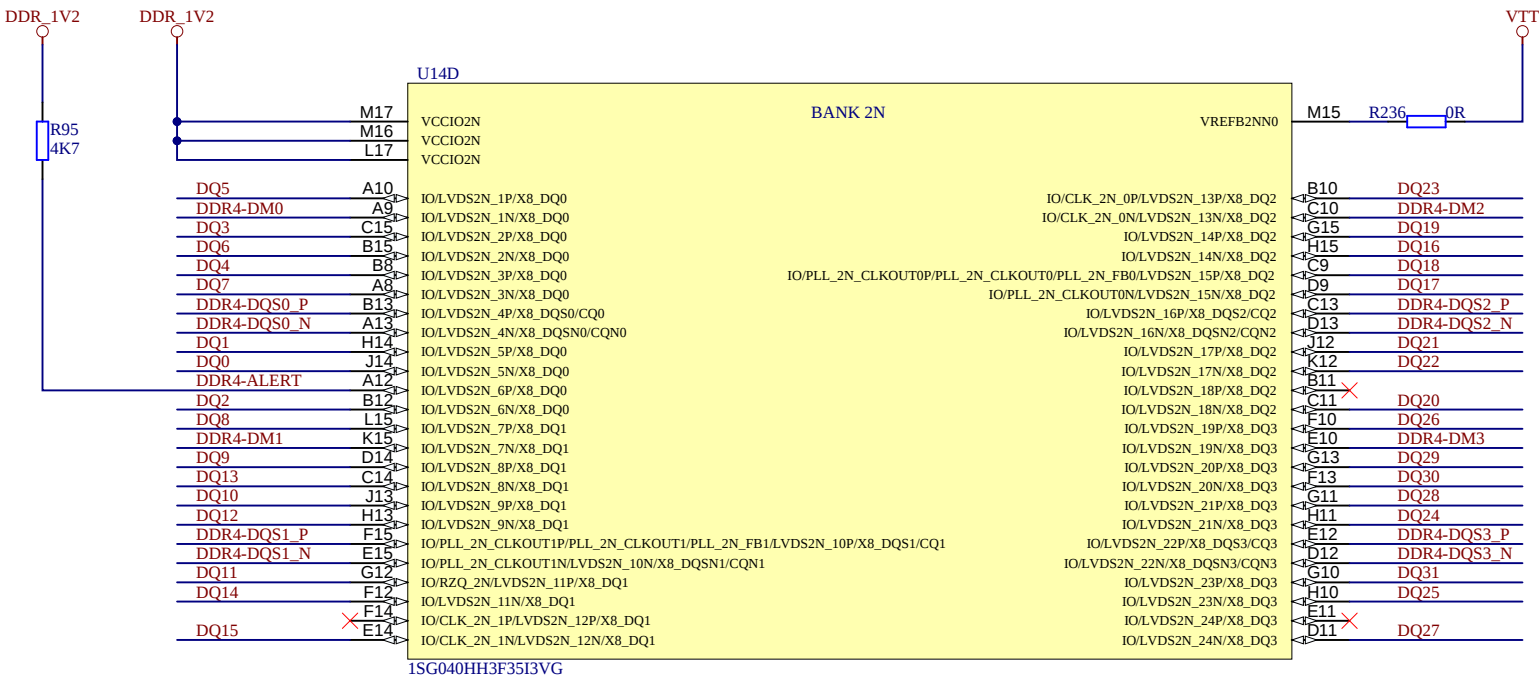
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Date: 2024-06-20	Copyright: Trenz Electronic GmbH	
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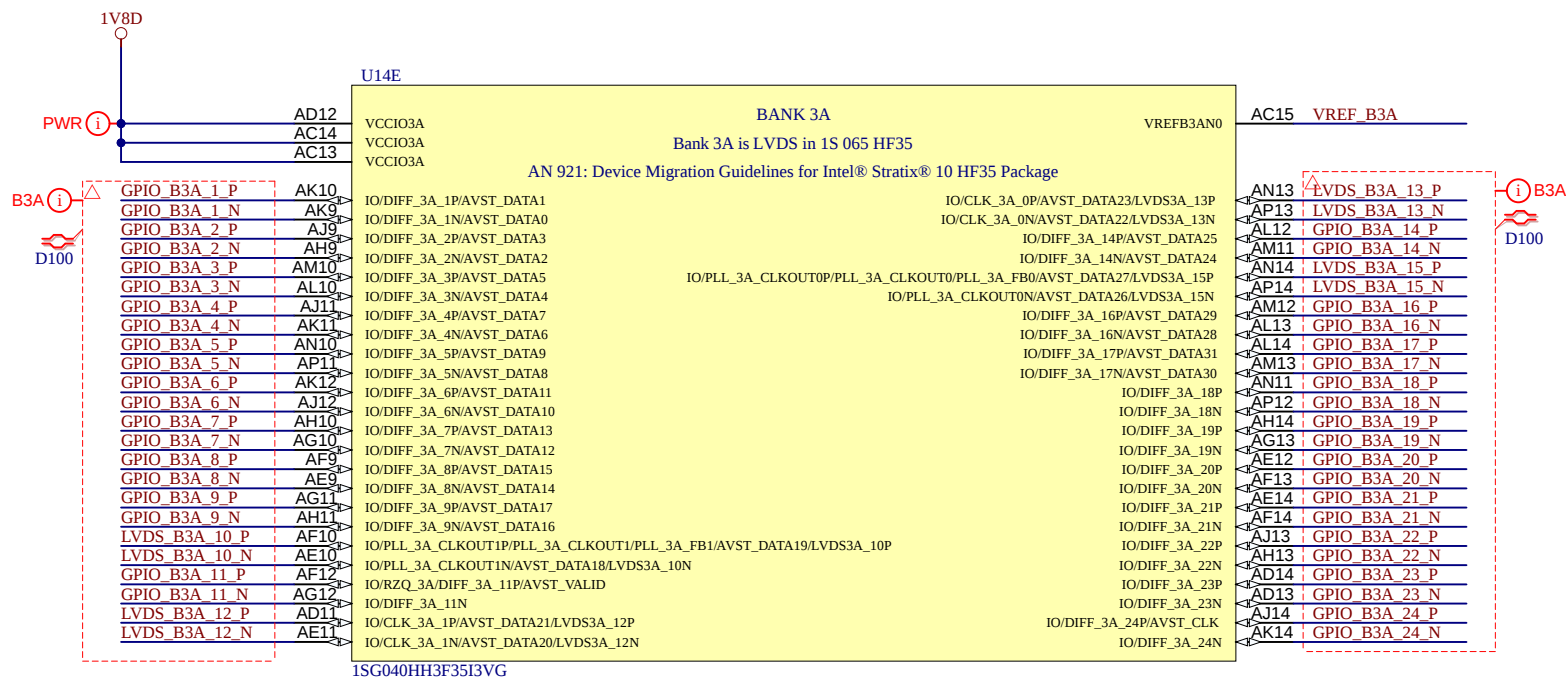
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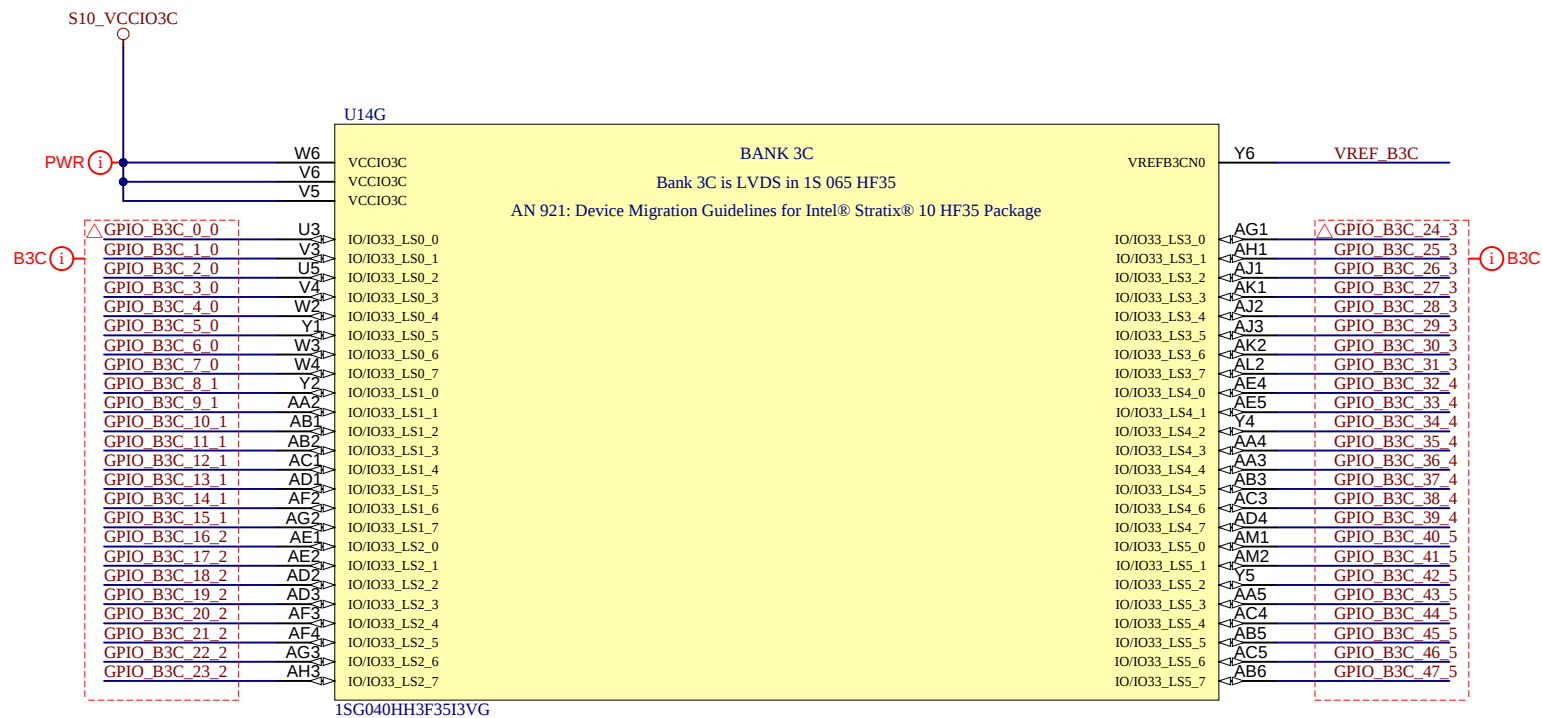




When I/O bank 3A is used for AVST x16 or AVST x32 configuration mode, you must connect the VCCIO3A power supply to the VCCIO_SDM power supply for proper device functionality.
(Intel® Stratix® 10 Device Family Pin Connection Guidelines, p. 20)



Title: TEI1000 - B3A			
A4	Number: TEI1000 ADI11-A	Rev. 02	
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Filename: Bank_3A.SchDoc			



48x high voltage I/Os



Title: TEI1000 - B3C		
A4	Number: TEI1000 ADI11-A	Rev. 02
Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Page26 of 43
Filename: Bank_3C.SchDoc		

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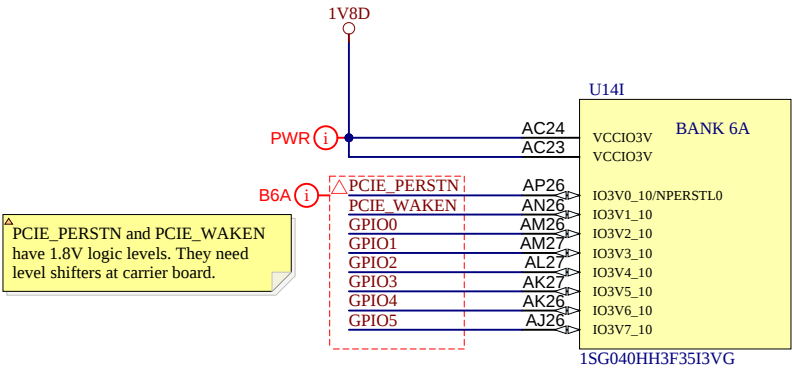
B

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PCIE_PERSTN and PCIE_WAKEN have 1.8V logic levels. They need level shifters at carrier board.

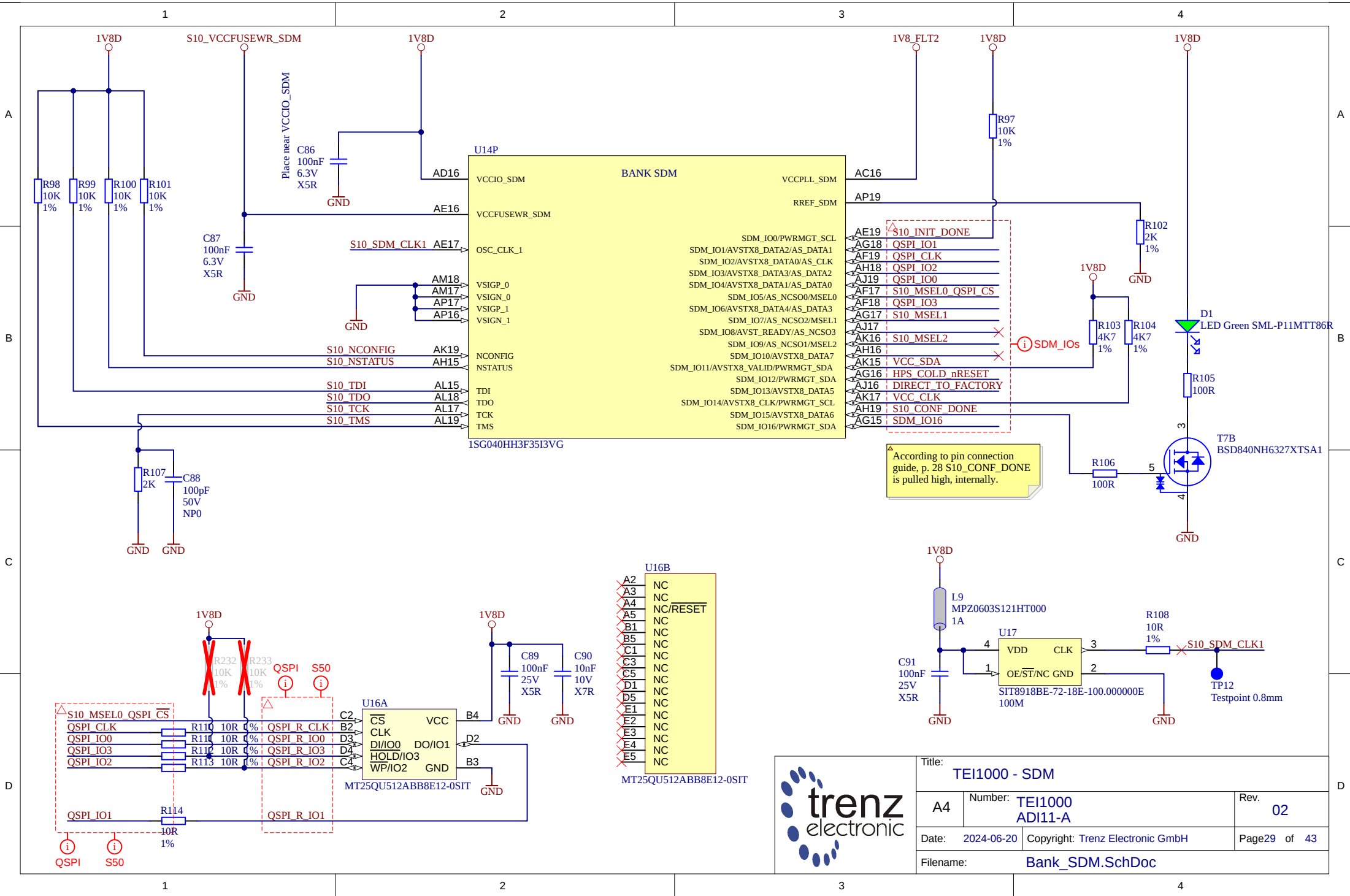
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Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Rev. 02
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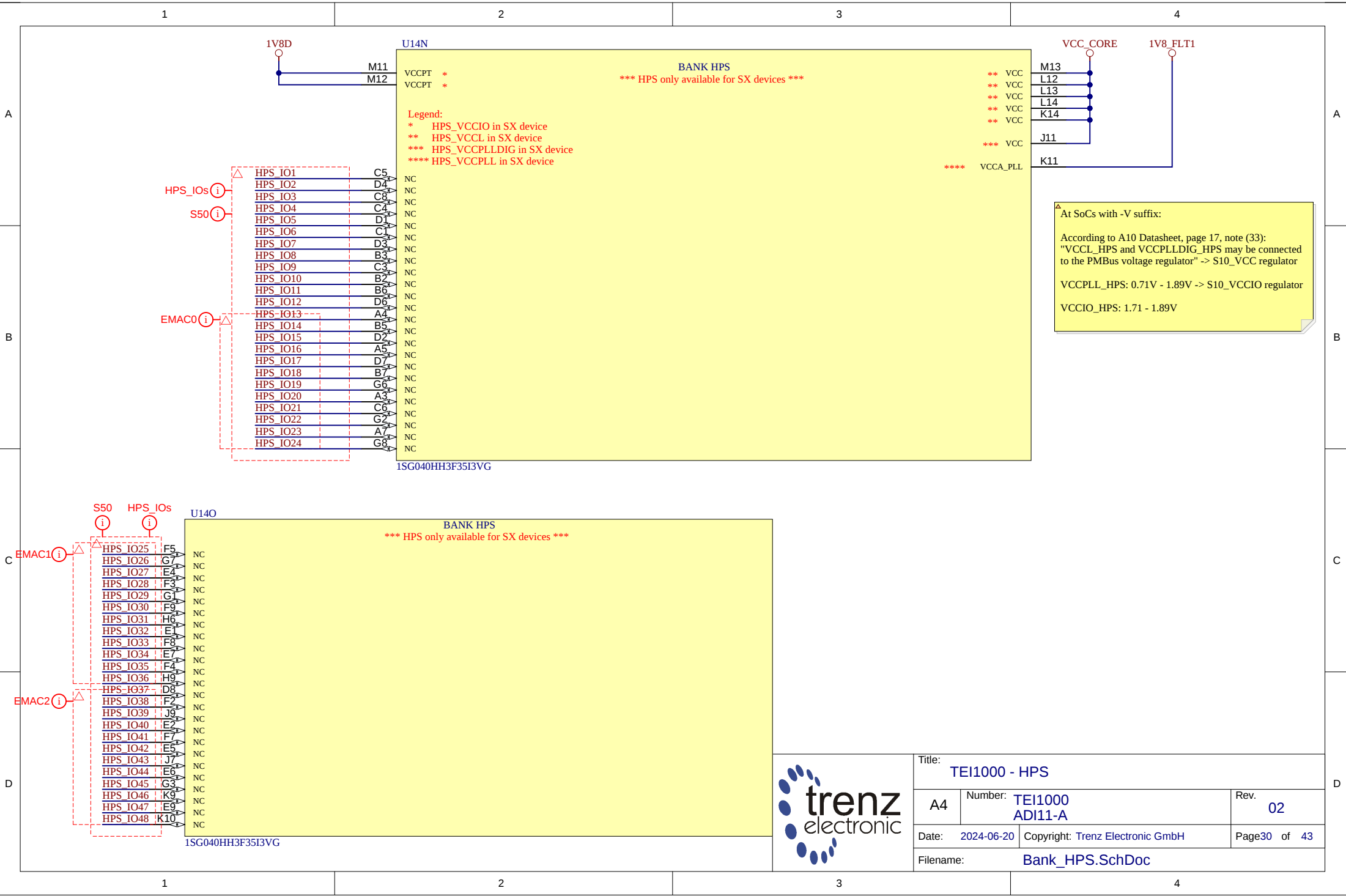
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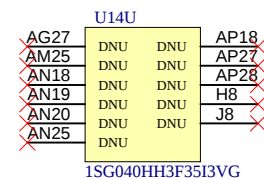
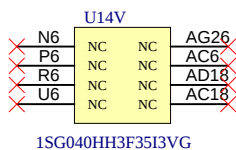
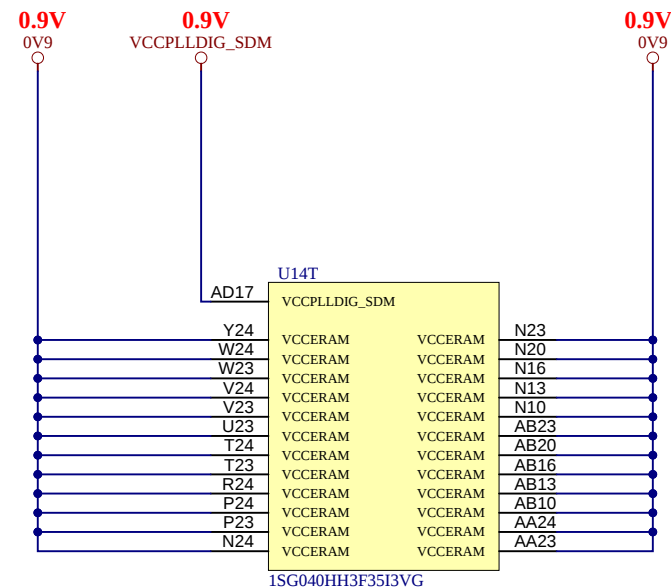
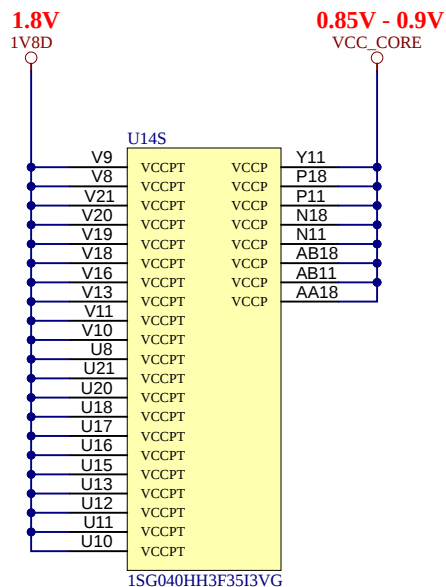
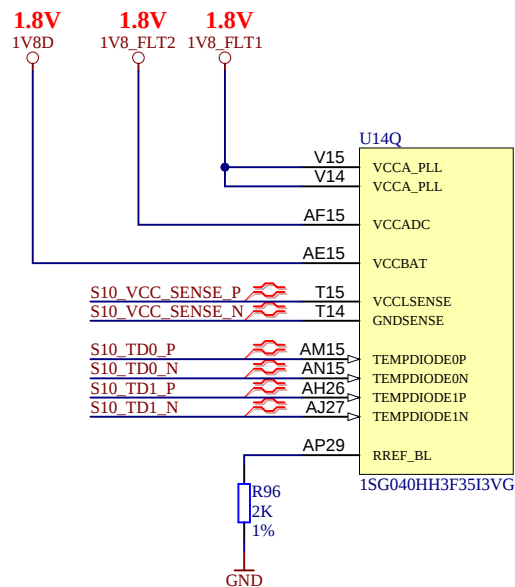
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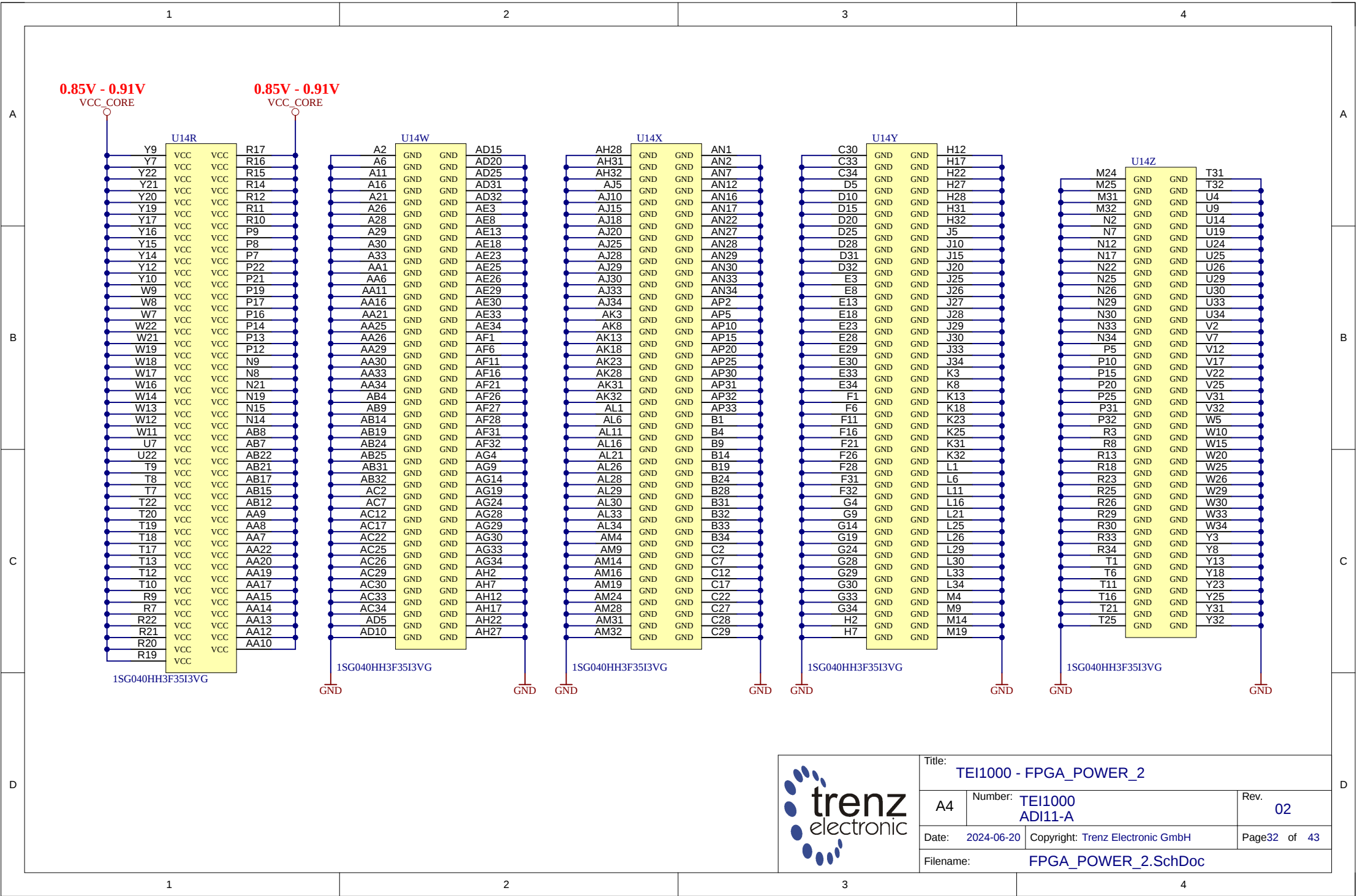


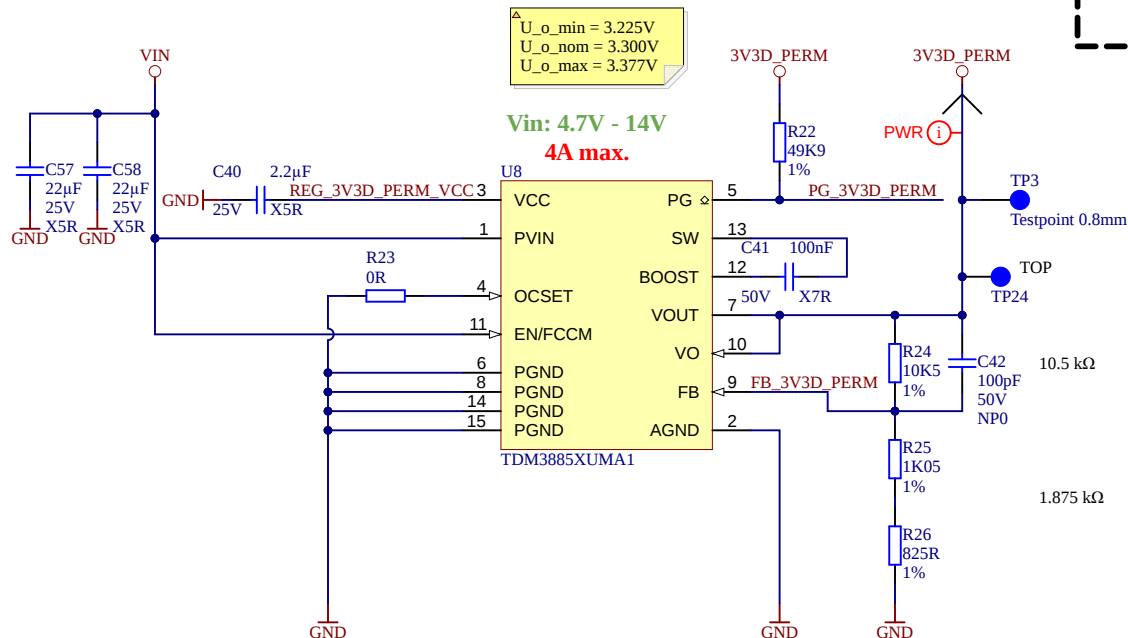
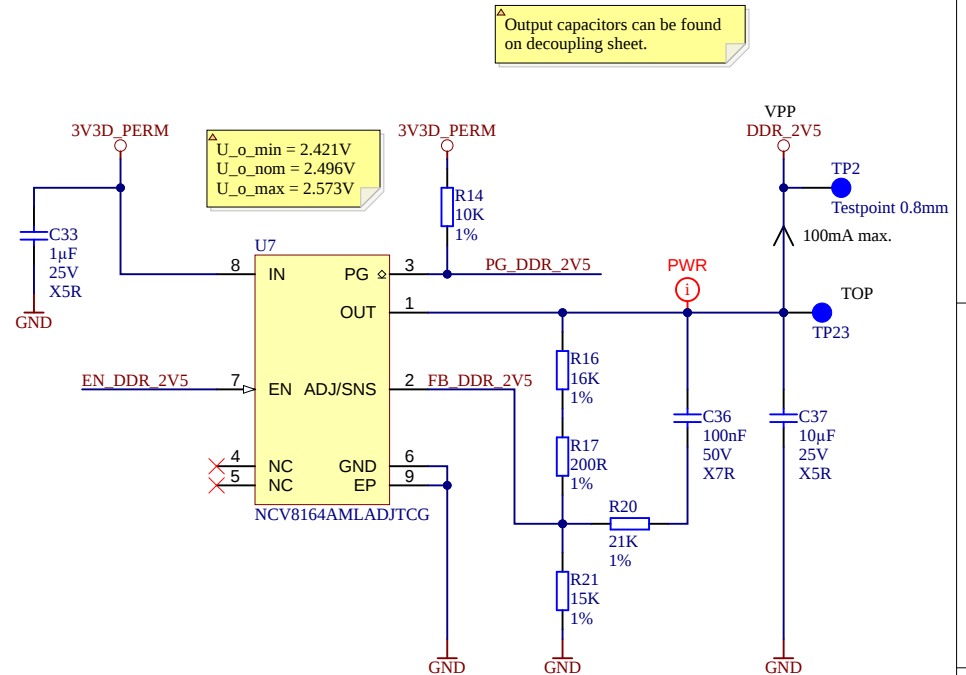
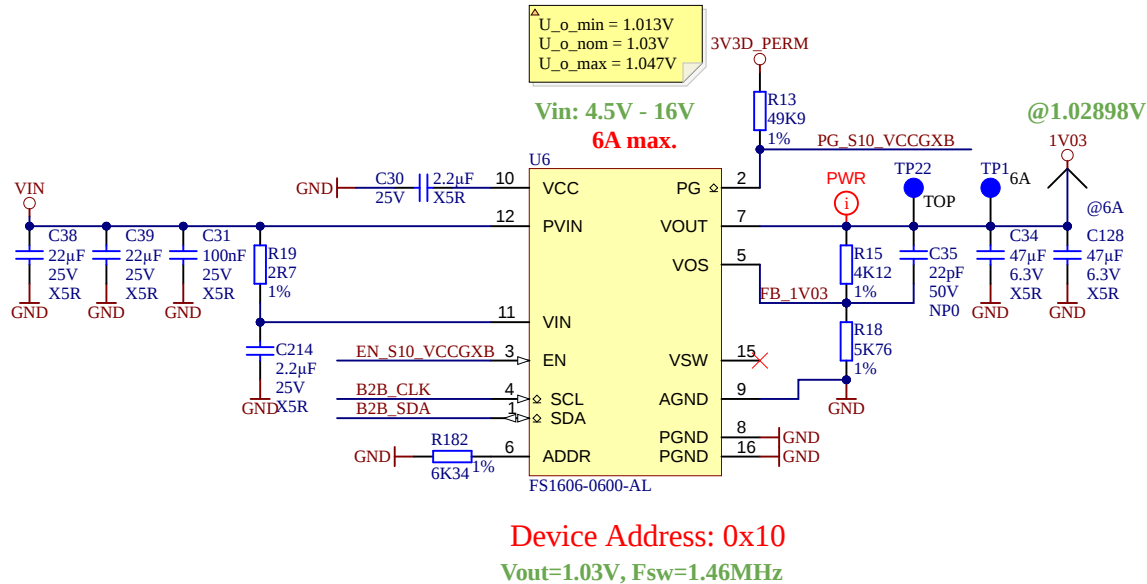


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Date: 2024-06-20	Copyright: Trenz Electronic GmbH		Page30 of 43
Filename: Bank_HPS.SchDoc			

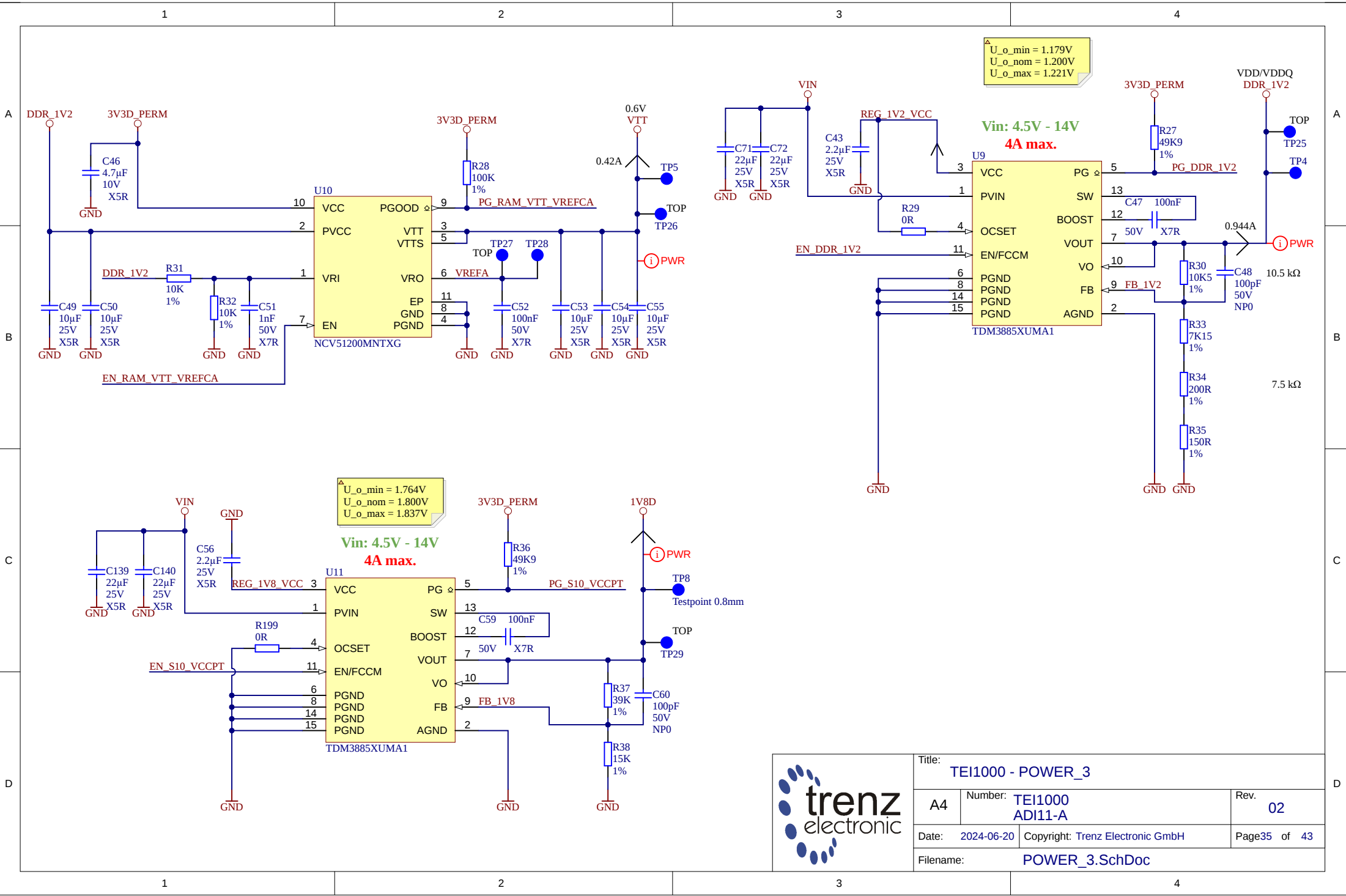


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Filename: FPGA_POWER_1.SchDoc		Page31 of 43	

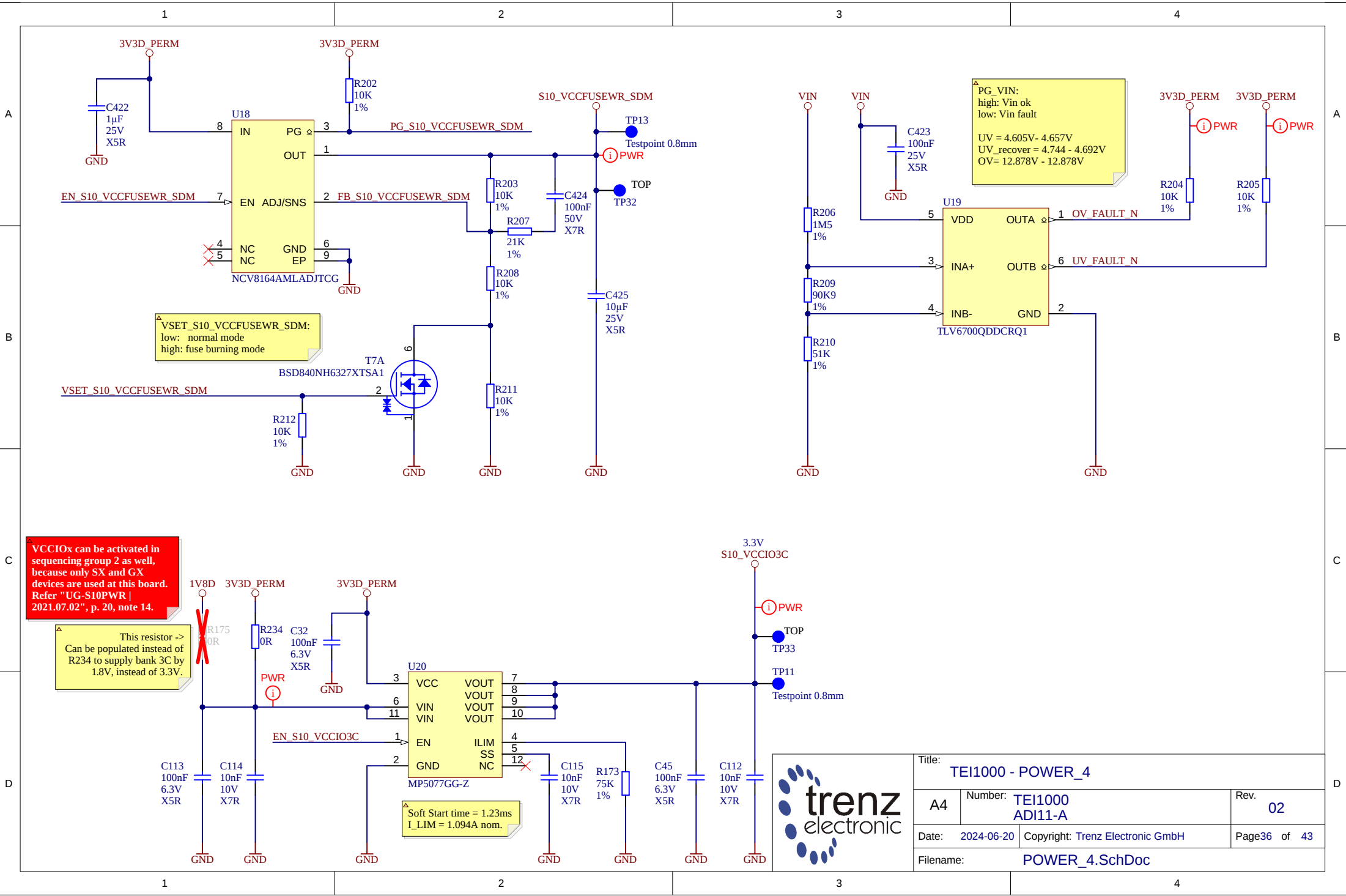




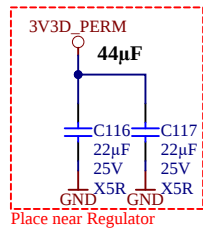
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Filename: POWER_2.SchDoc			



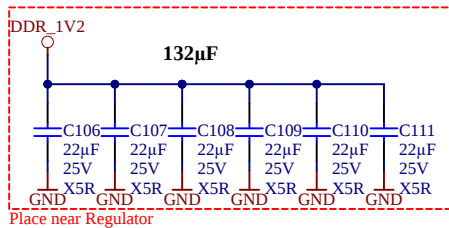
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Filename: POWER_3.SchDoc			



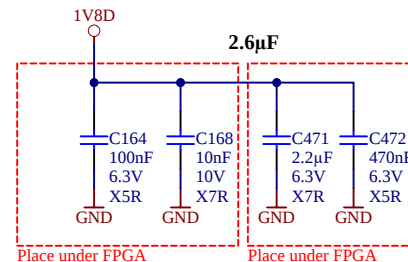
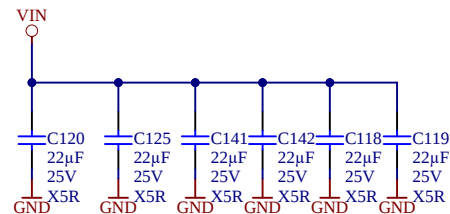
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Date: 2024-06-20	Copyright: Trenz Electronic GmbH		Page 36 of 43
Filename: POWER_4.SchDoc			



Place near Regulator



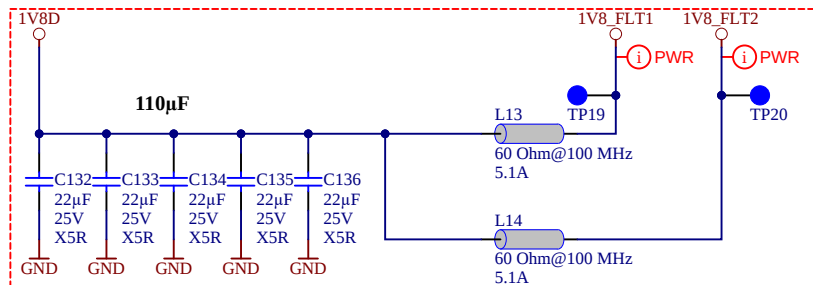
Place near Regulator



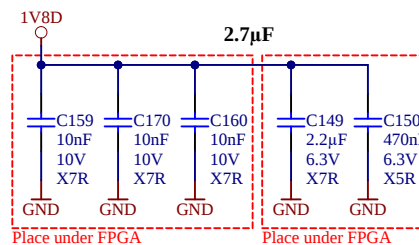
Place under FPGA

Place under FPGA

For supply of bank 6A



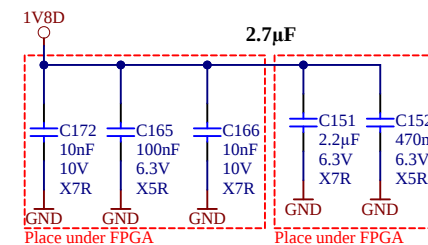
Place near Regulator



Place under FPGA

Place under FPGA

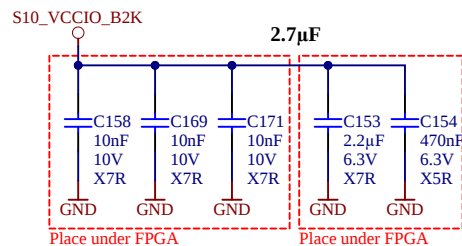
For supply of bank 3A



Place under FPGA

Place under FPGA

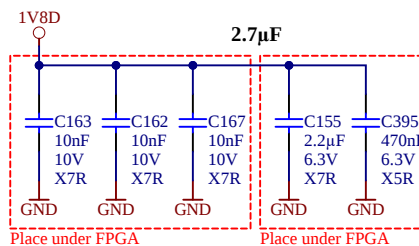
For supply of bank 3B



Place under FPGA

Place under FPGA

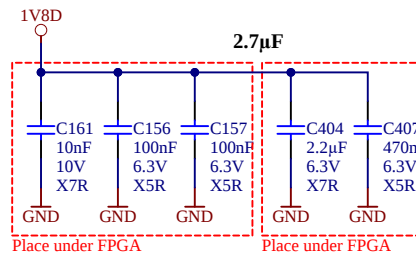
For supply of bank 2K



Place under FPGA

Place under FPGA

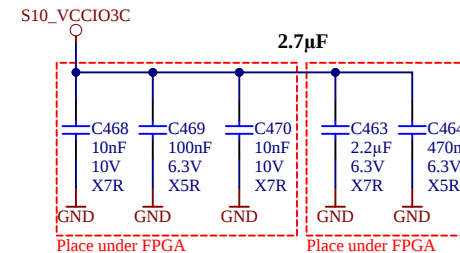
For supply of bank 2L



Place under FPGA

Place under FPGA

For supply of bank 3D



Place under FPGA

Place under FPGA

For supply of bank 3C



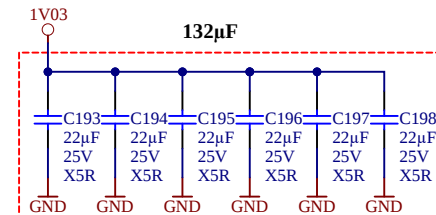
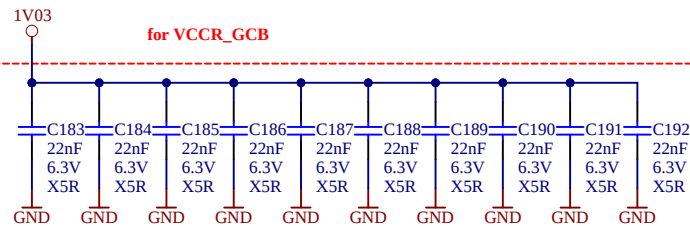
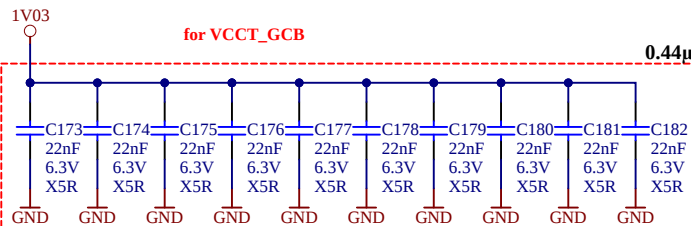
Title: TEI1000 - POWER_Decoupling_1		
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1

2

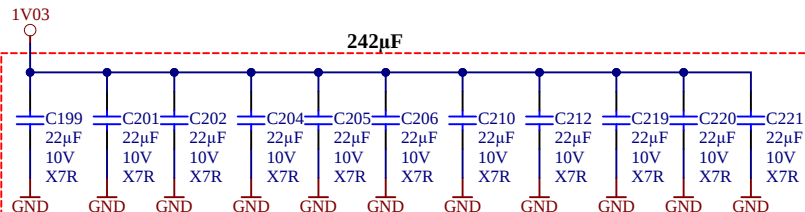
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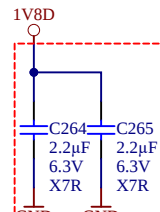


Place under FPGA

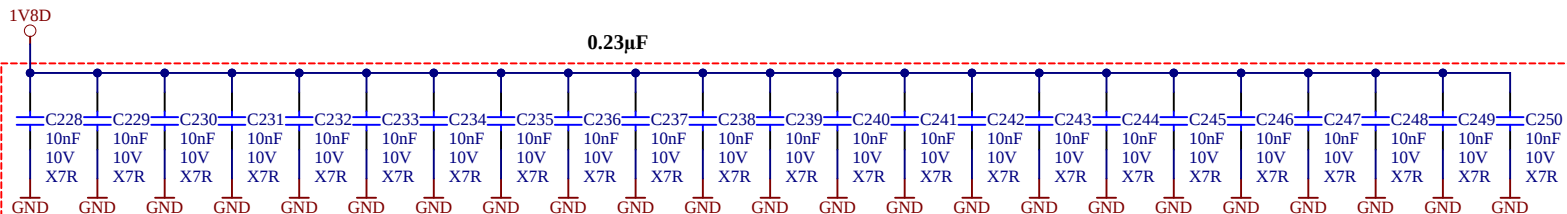
Place near Regulator



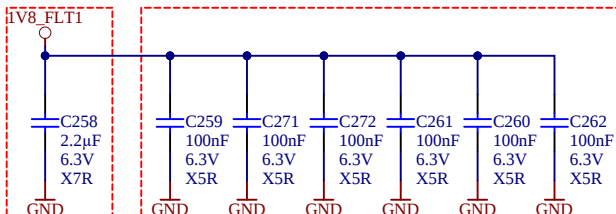
Place near FPGA



Place near FPGA

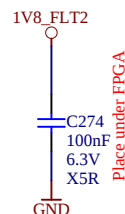


Place under FPGA



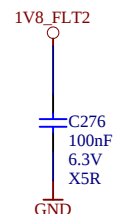
Place near FPGA

Place near FPGA



for VCCPLL_SDM

Place under FPGA



for VCCADC

Place under FPGA



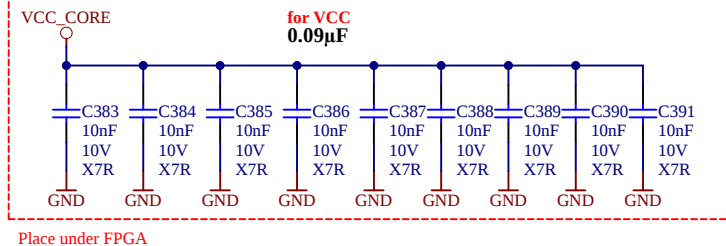
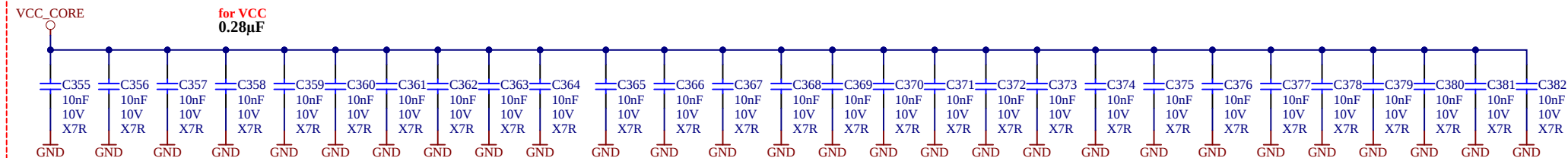
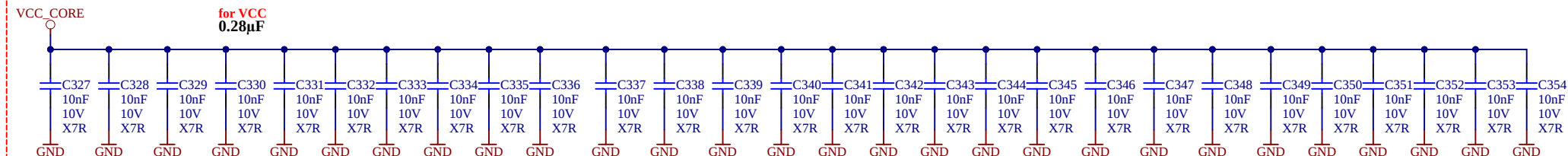
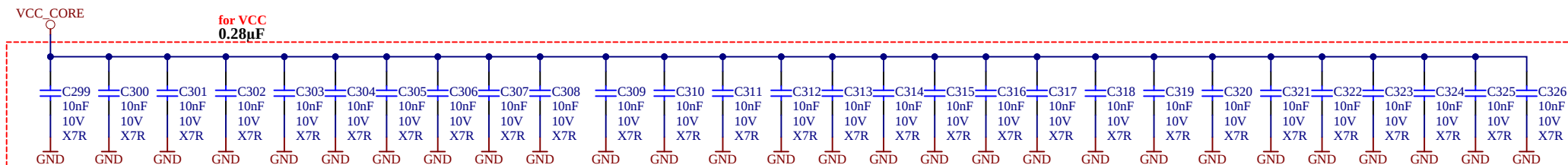
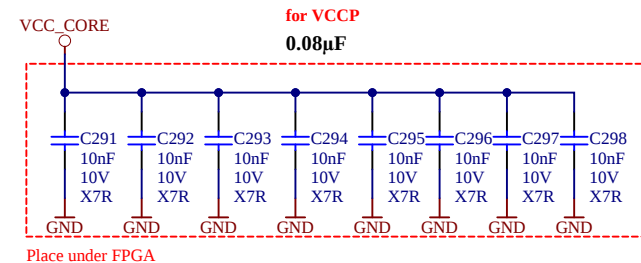
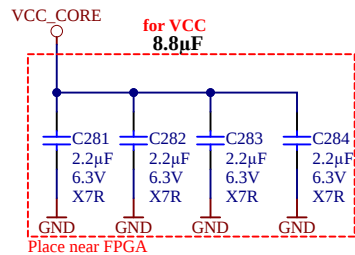
Title: TEI1000 - POWER_Decoupling_2		
A4	Number: TEI1000 ADI11-A	Rev. 02
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1

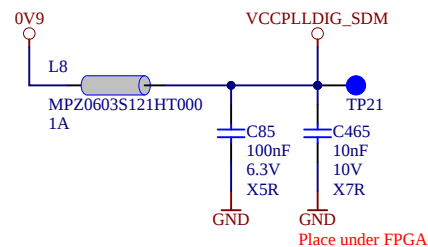
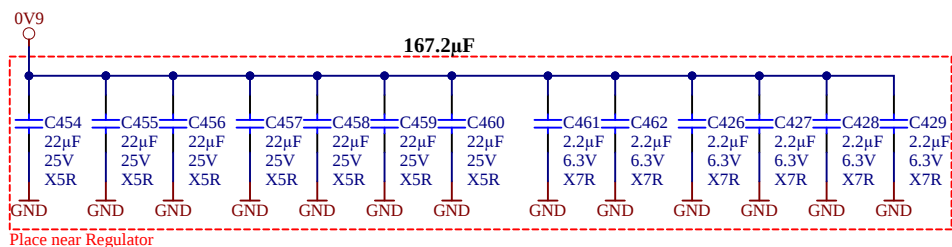
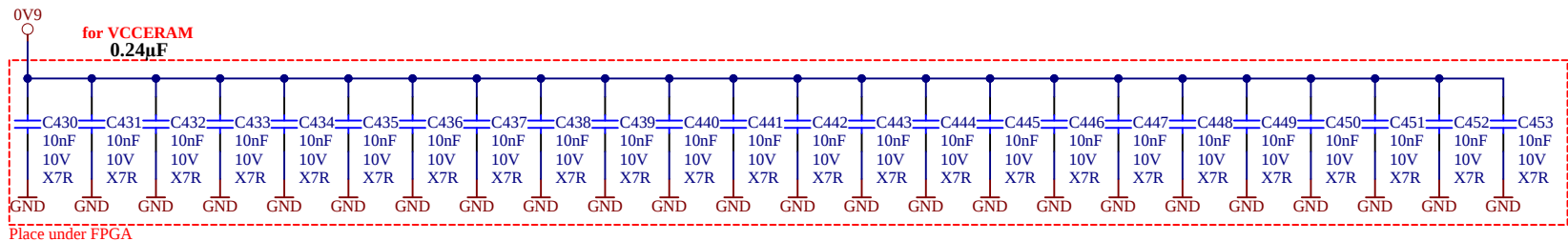
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3

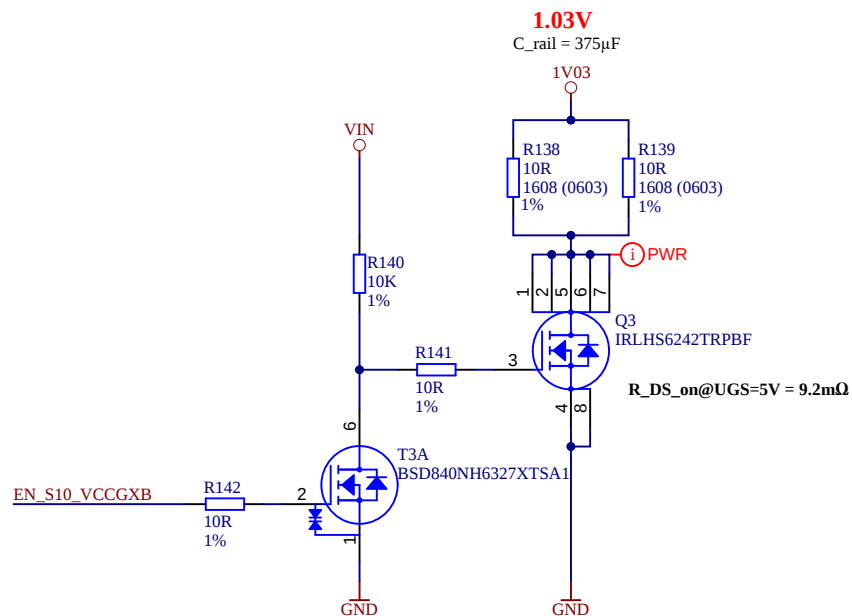
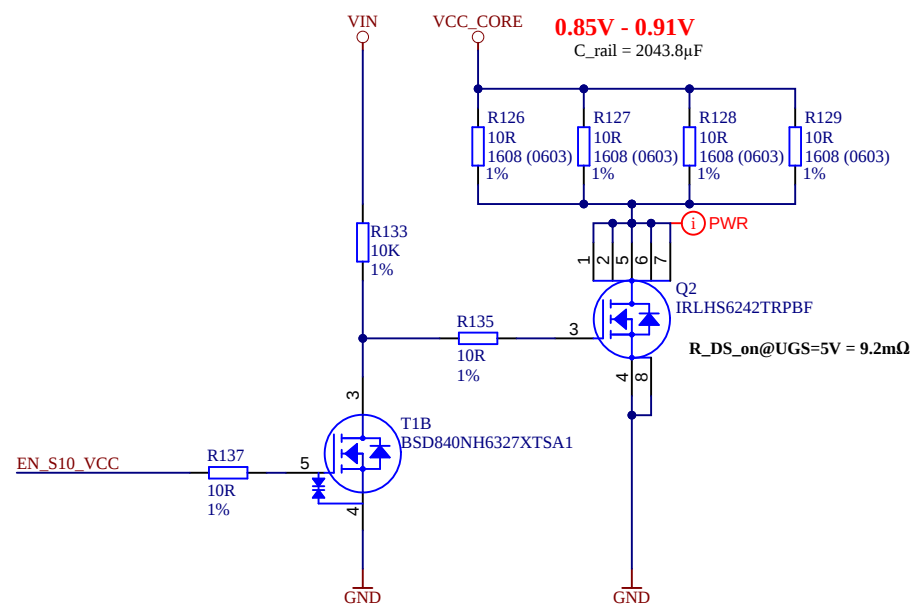
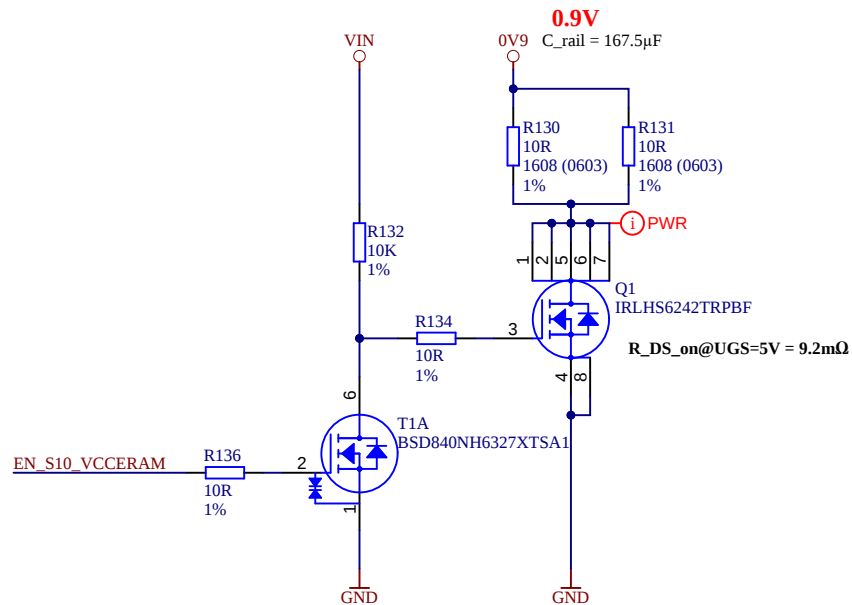
4



Title: TEI1000 - POWER_Decoupling_3		
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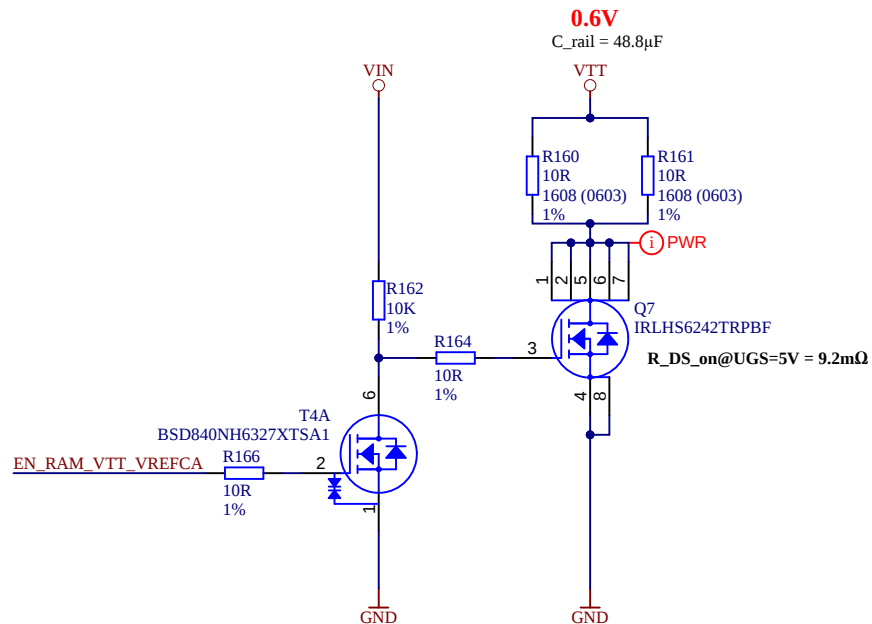
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	A4	Number: TEI1000 ADI11-A	Rev. 02
	Date: 2024-06-20	Copyright: Trenz Electronic GmbH	Page40 of 43
	Filename: POWER_Decoupling_4.SchDoc		



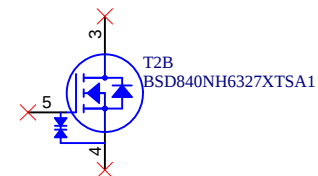
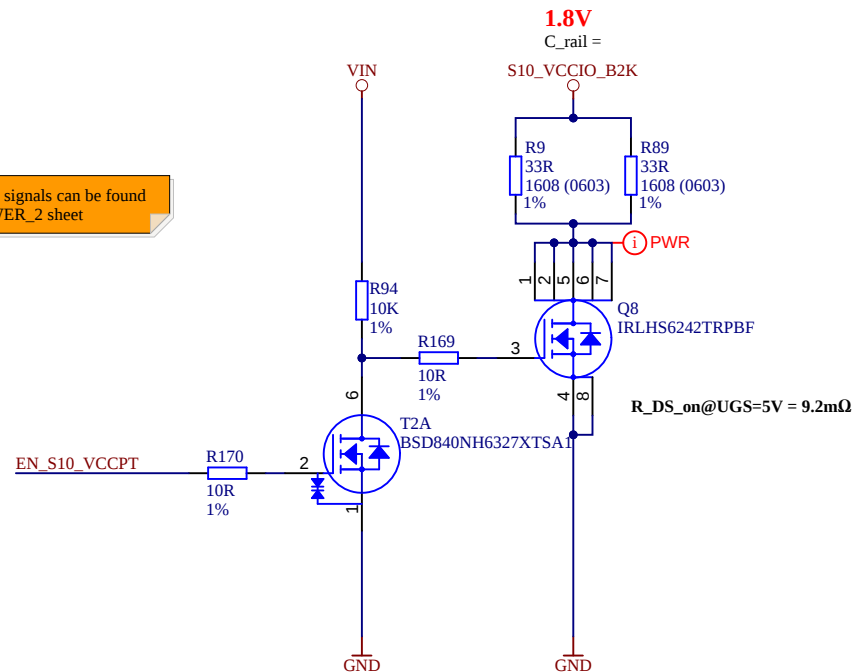
Δ Pull-downs of enable signals can be found on POWER_1 / POWER_2 sheet



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^A Pull-downs of enable signals can be found on POWER_1 / POWER_2 sheet



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